



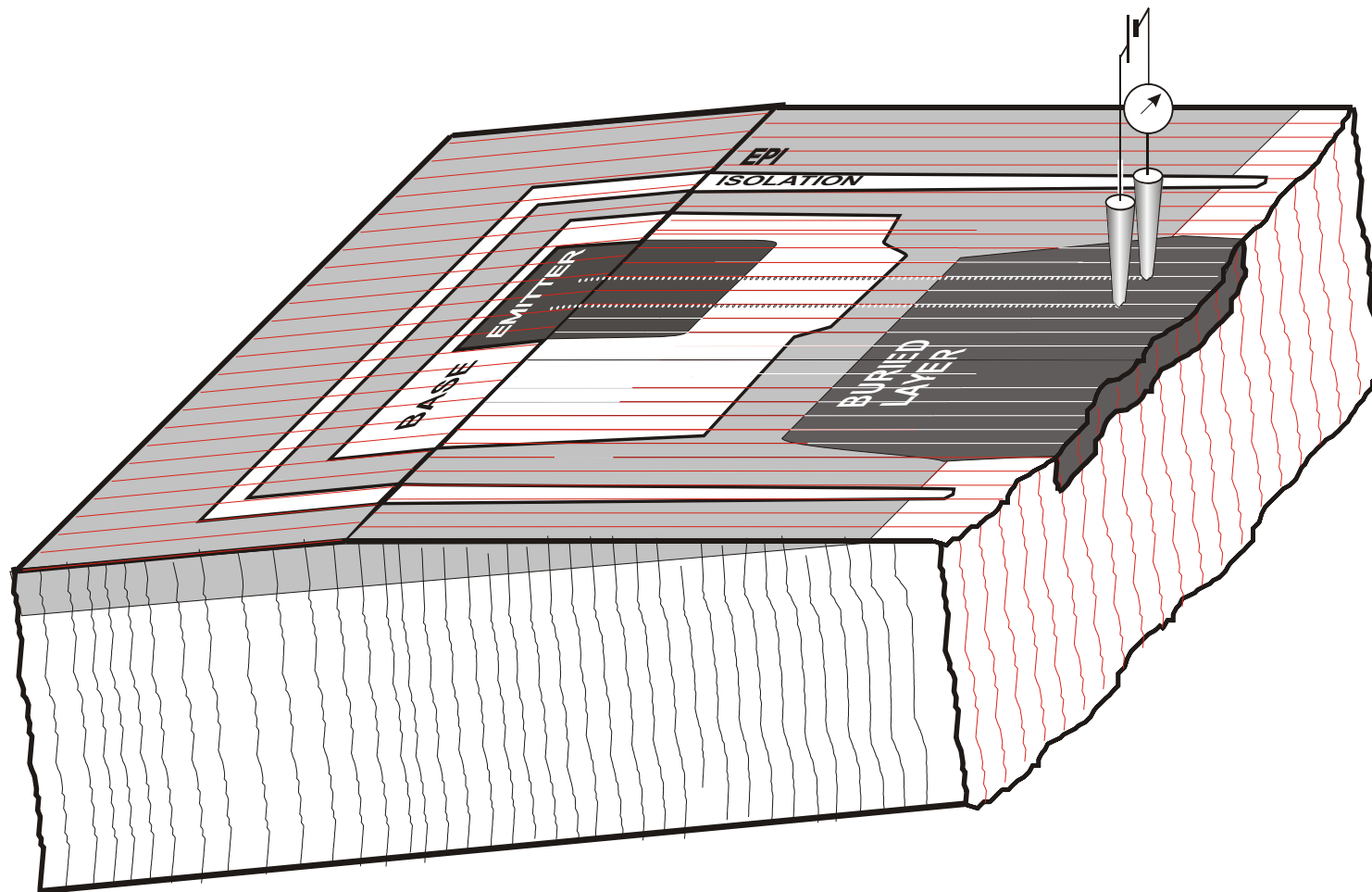
*An Introduction to  
Spreading Resistance Analysis  
and its Application in the  
Semiconductor Industry*

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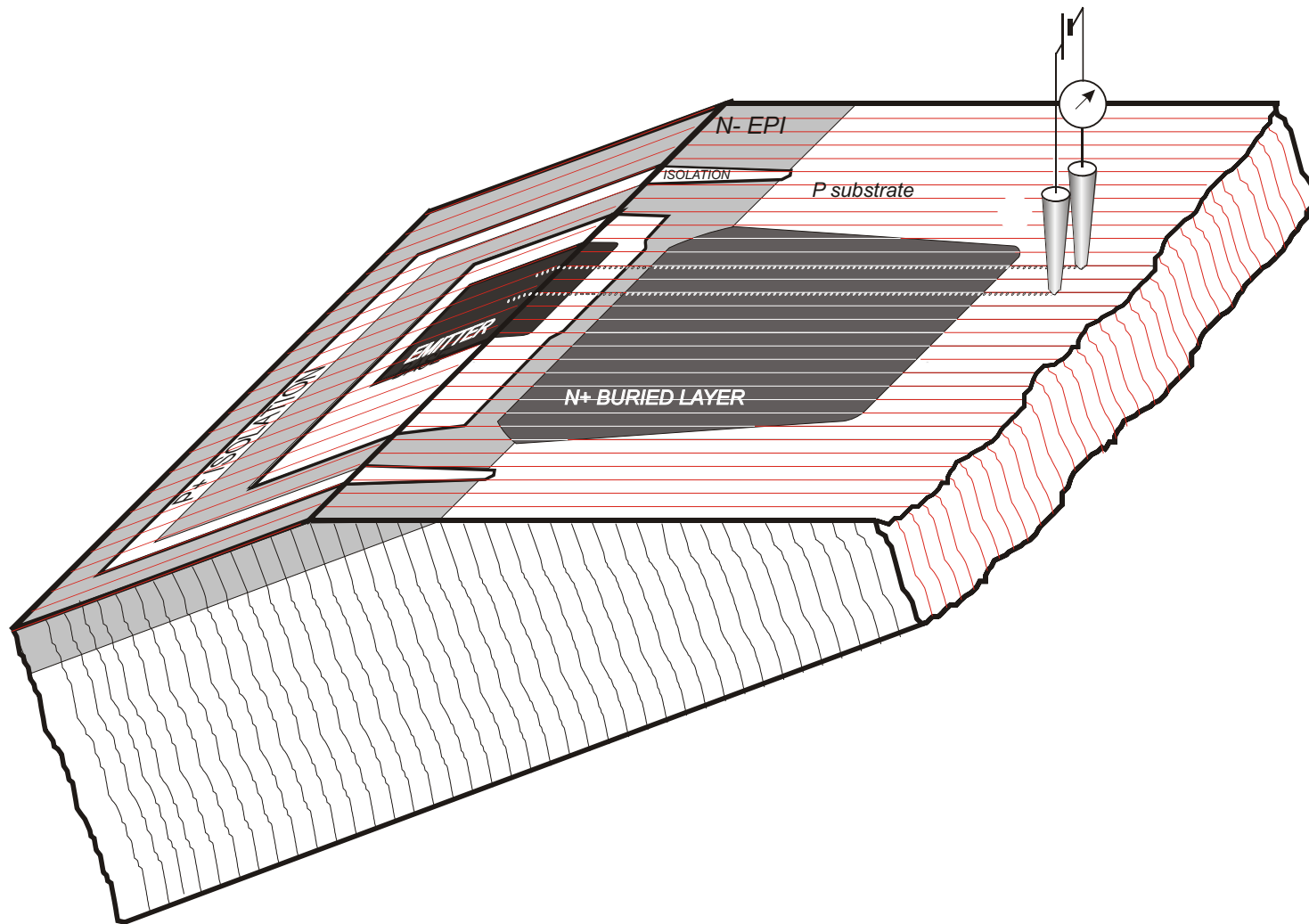
## ***Filling out our request form:***

1. Solecon Labs privacy policy.
2. Provide us with as much information as possible.
3. An appropriate bevel angle is needed.
4. Solecon strives for over 20 data points per layer.
5. A shallow emitter at  $.2\mu\text{m}$  on base at  $.4\mu\text{m}$  on epi/buried layer at  $5.5\mu\text{m}$  on p-type substrate. What are you really interested in?

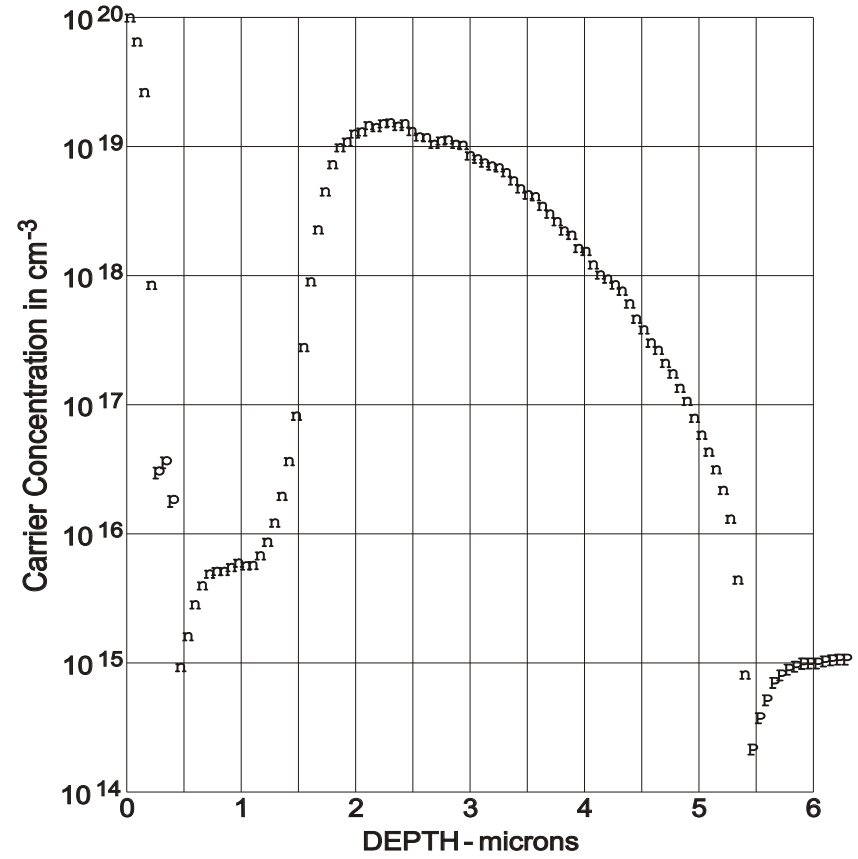
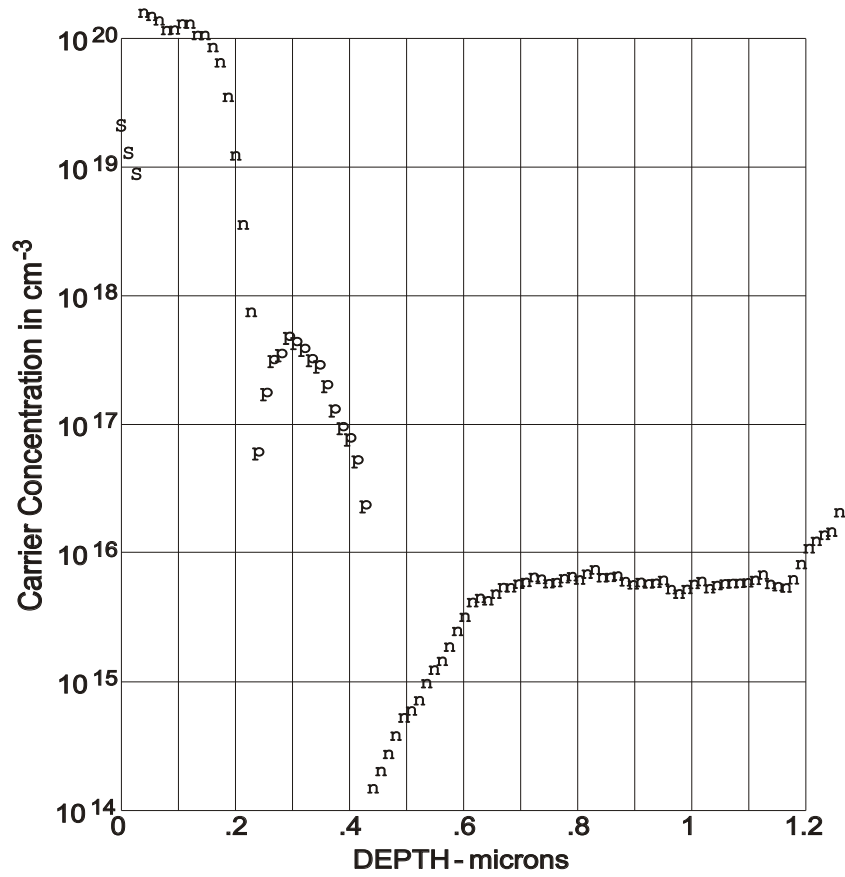
# Shallow Profile of the Bipolar Structure



# Deep Profile of the Bipolar Structure



# Bipolar Transistor



## ***How much of the sample do we need?***

1. We measure from full wafers to a millimeter square.
2. Pattern wafers and backups.

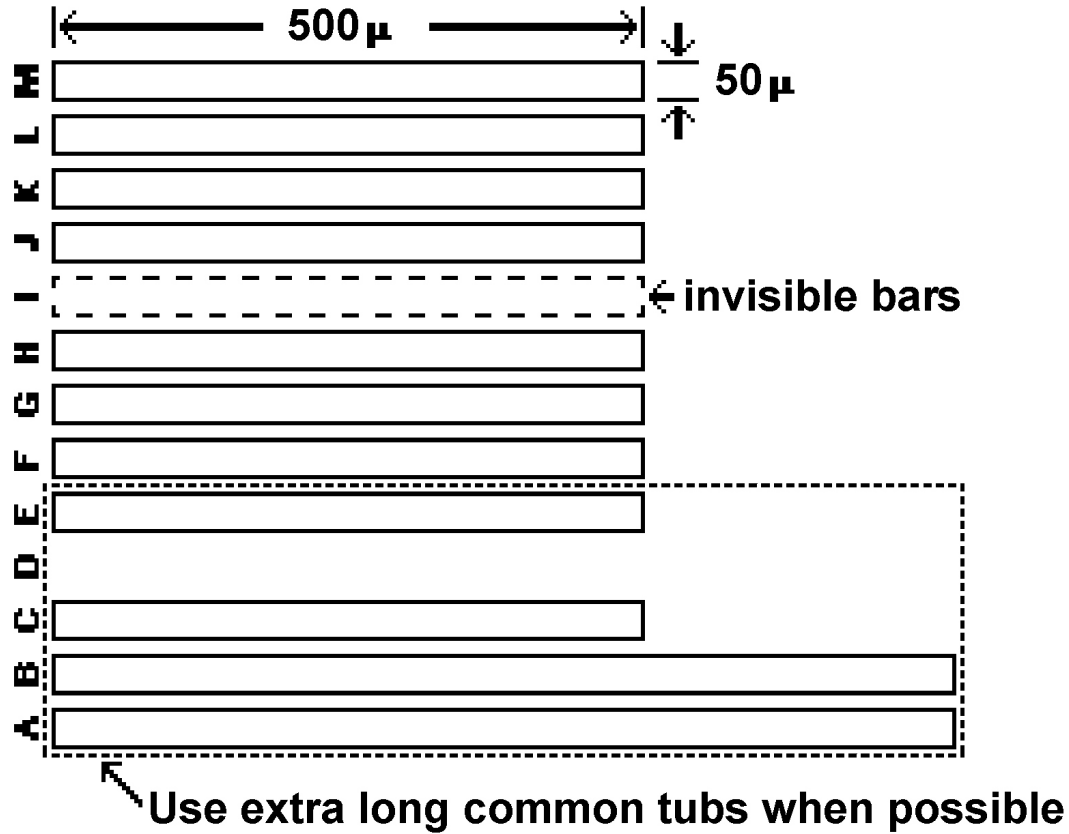
### ***Beveling:***

1. Your samples are mounted on angled beveling blocks.
2. Samples should be beveled immediately before probing, to avoid interference from native oxide.

### ***Size of pattern:***

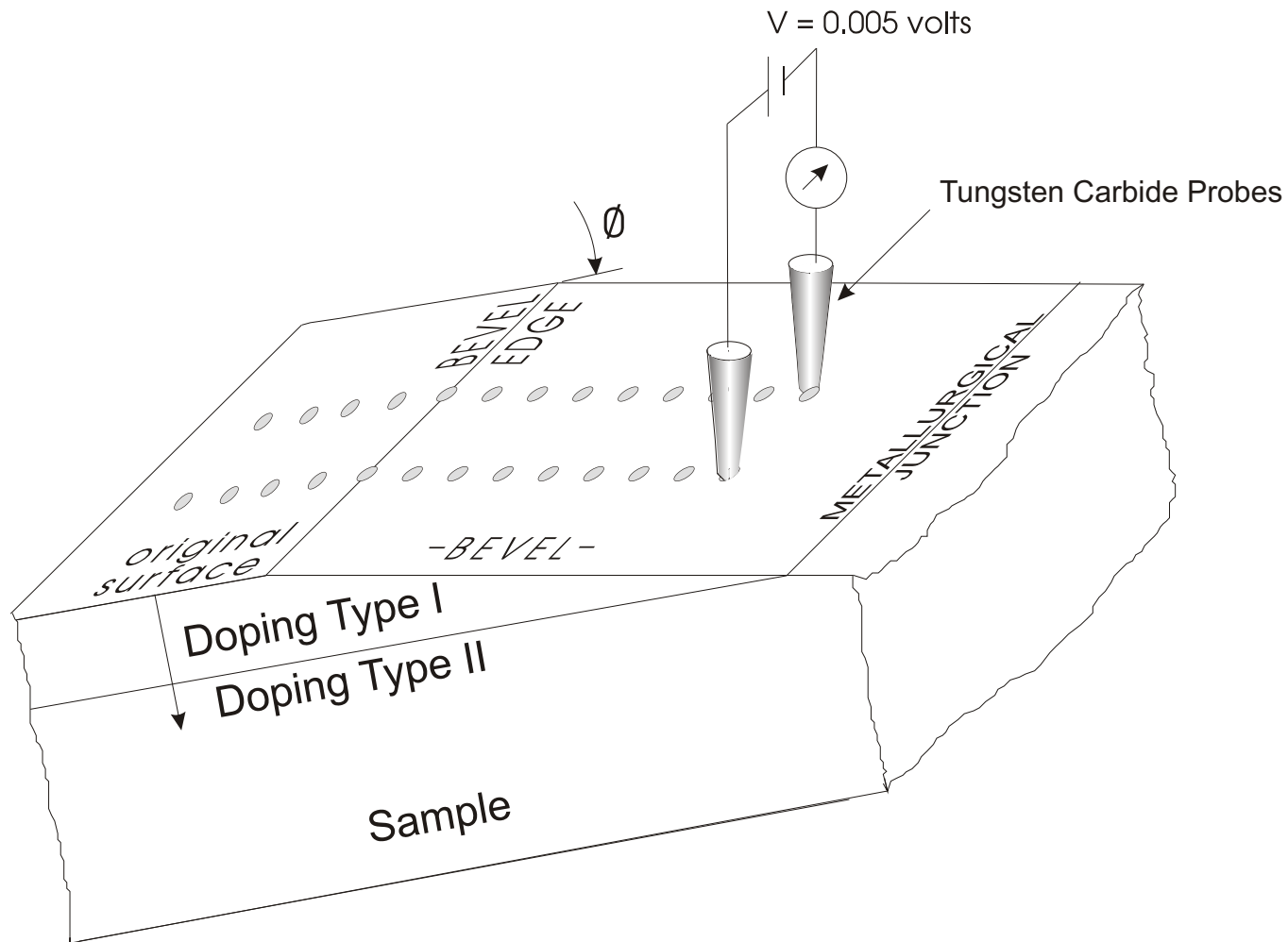
1. Our minimum requirements are 20 $\mu$ m wide x 100 $\mu$ m long.
2. The smaller the pattern size the greater the compromise.
3. For this reason we suggest dedicated spreading resistance test patterns which are 50 x 500 $\mu$ m.

# Dedicated SRA Test Patterns



**Recommended for Scribeline use Only**

## ***Schematic diagram of a spreading resistance measurement on a beveled sample***

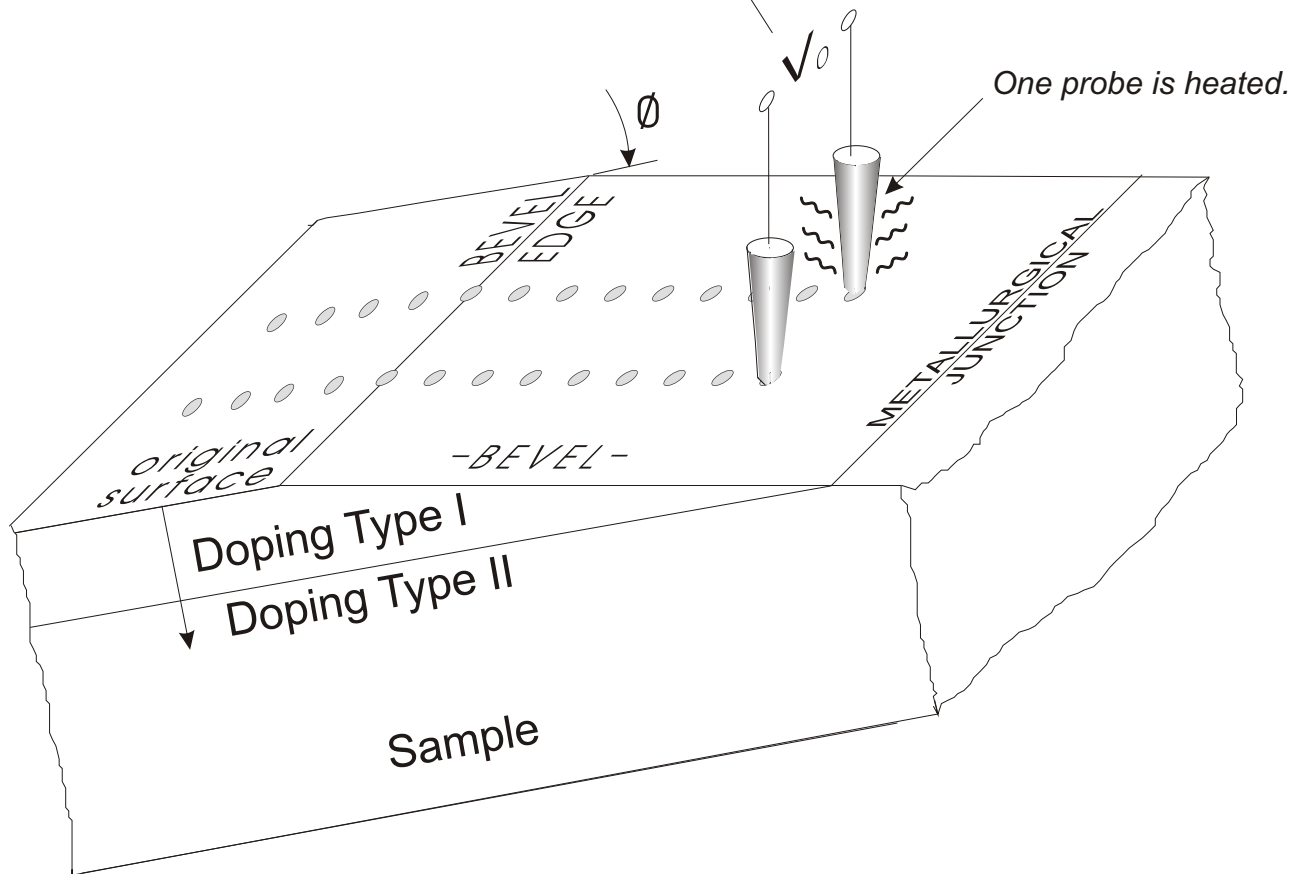




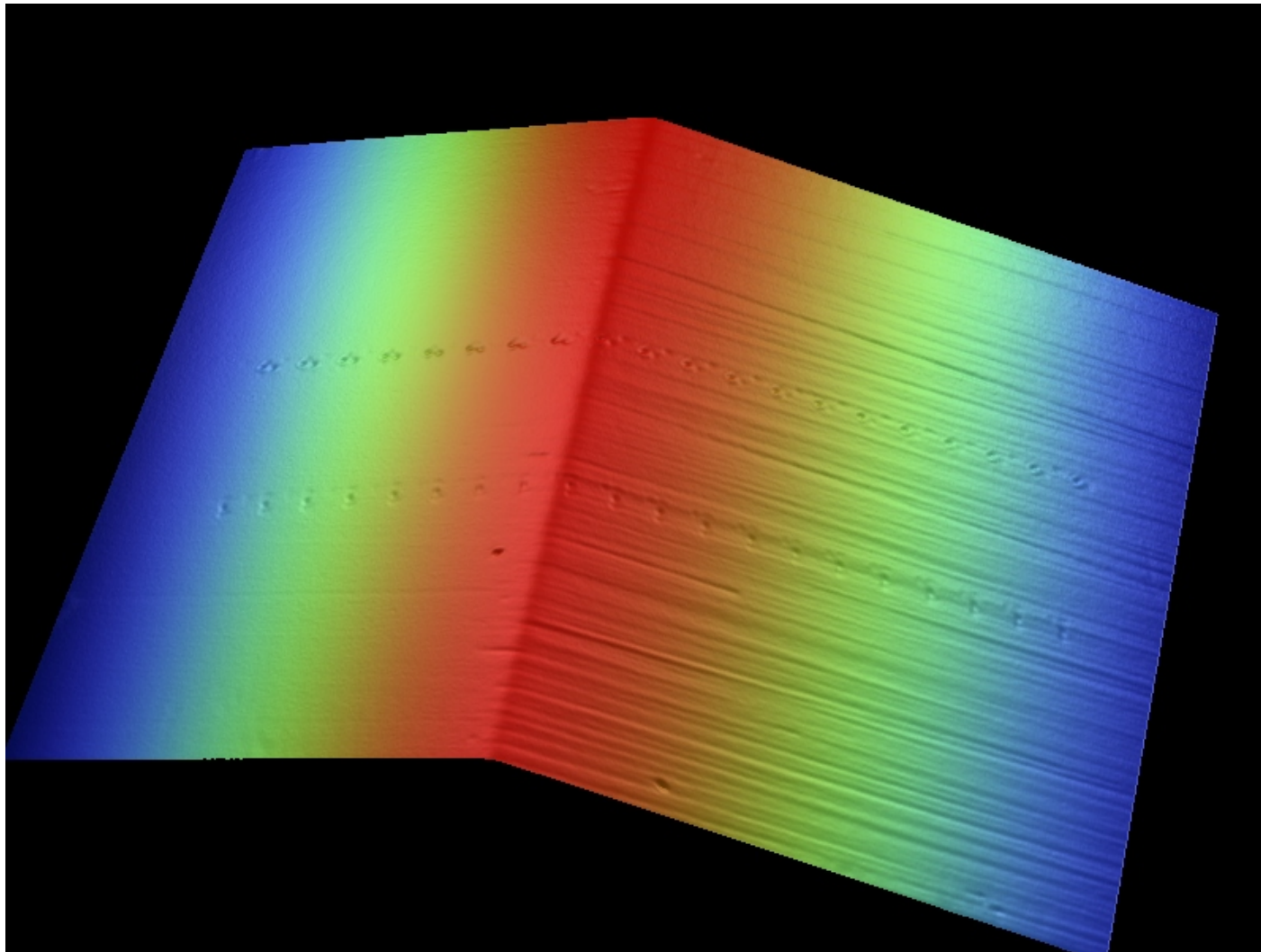
# **Carrier Type Determination**

**With a Few Modifications, the Spreading Resistance Set-Up Can Determine "N" or "P".**

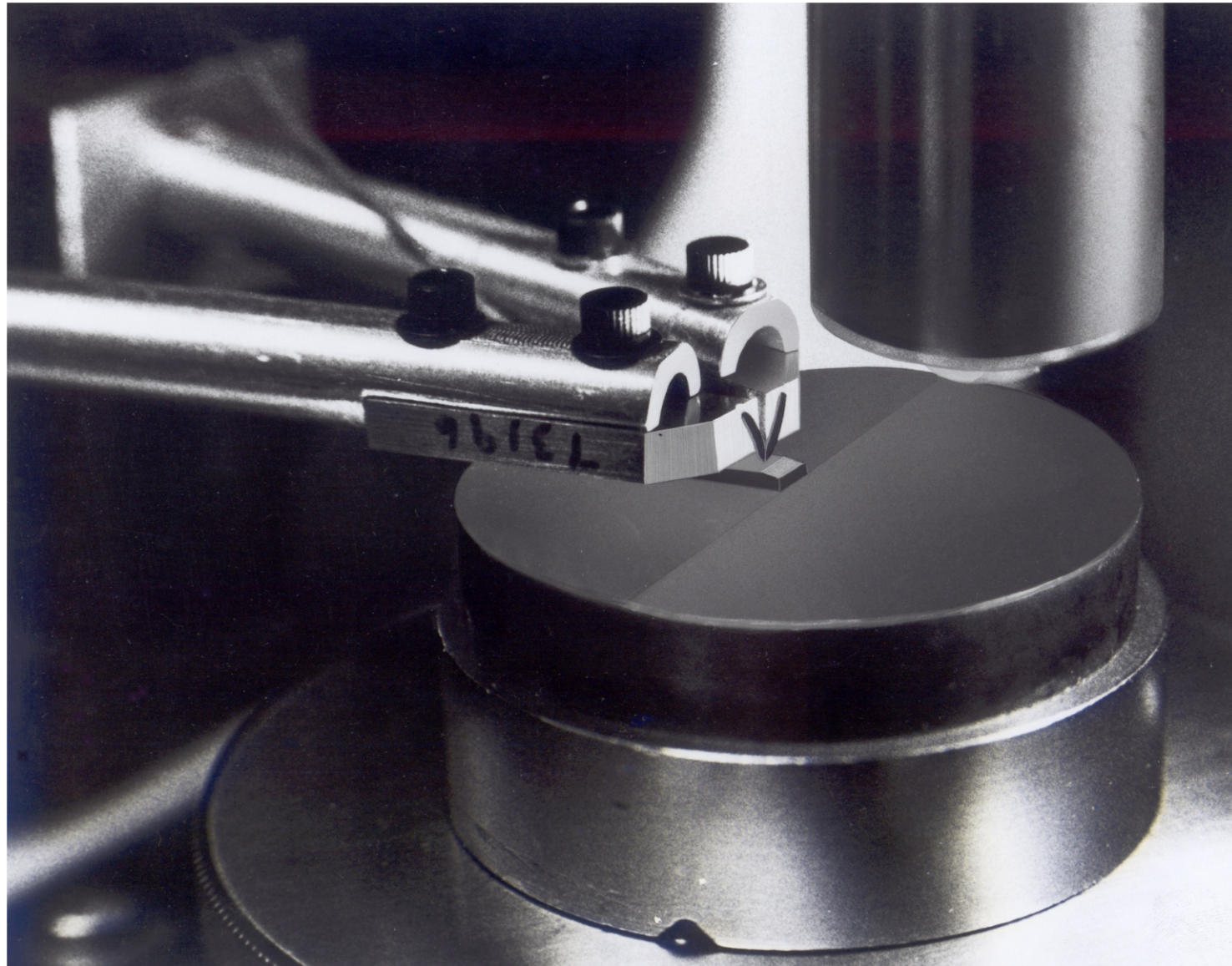
*Polarity and magnitude of the open circuit (Seebeck) voltage determined*



***Optical Profilometer view of a spreading resistance measurement on a beveled sample***



## ***Birds Eye View of SRA Sample and Probes***

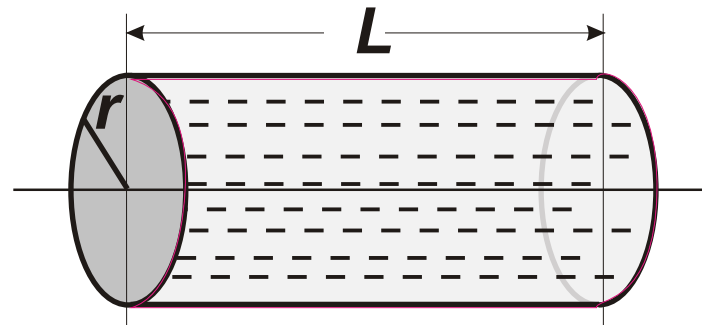


## ***Probing***

1. 2 probe tips made of tungsten carbide are used.
2. The probe tips are shaped so that they can be positioned within 20um of each other.
3. Each probe tip is mounted on the end of a separate arm.
4. Each arm pivots on a kinematic bearing system that eliminates lateral motion or "scrubbing" as it contacts the sample.
5. Probe tips are lowered gently onto the sample.
6. Because of the small contact area, pressure is in excess of a million pounds per square inch.
7. 5 millivolts are applied across the probes and the resistance is measured.

## LINEAR CURRENT FLOW

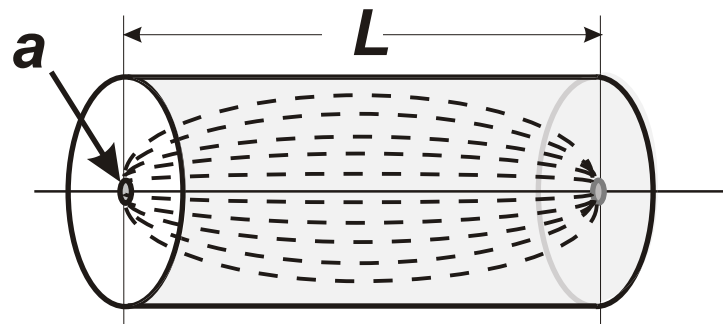
$$R = \frac{\rho L}{r^2}$$



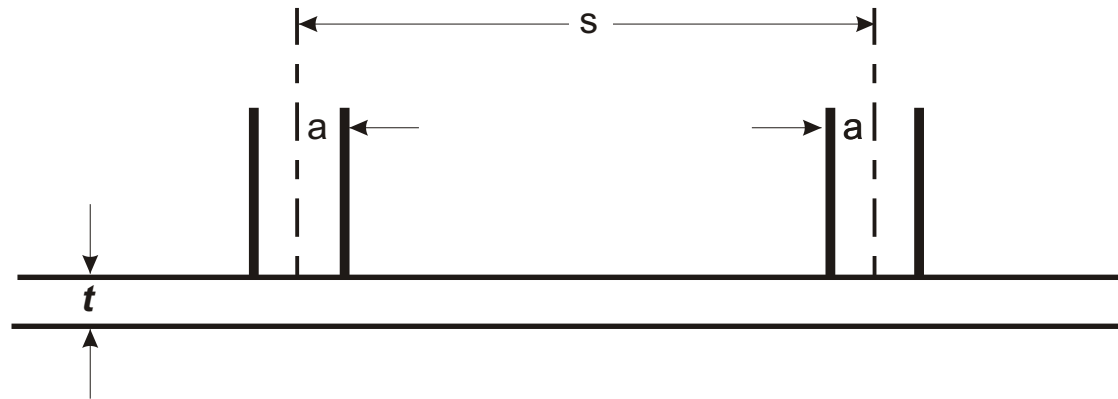
where  $\rho$  is the bulk resistivity in ohm-cm

## SPREADING RESISTANCE

$$R = \frac{\rho L}{2a}$$



## Two Probes on a Thin Layer ( $t < a$ ):



$$R = \frac{1}{t} \ln \frac{s}{a}$$

D. H. Dickey, NBS SP 400-48

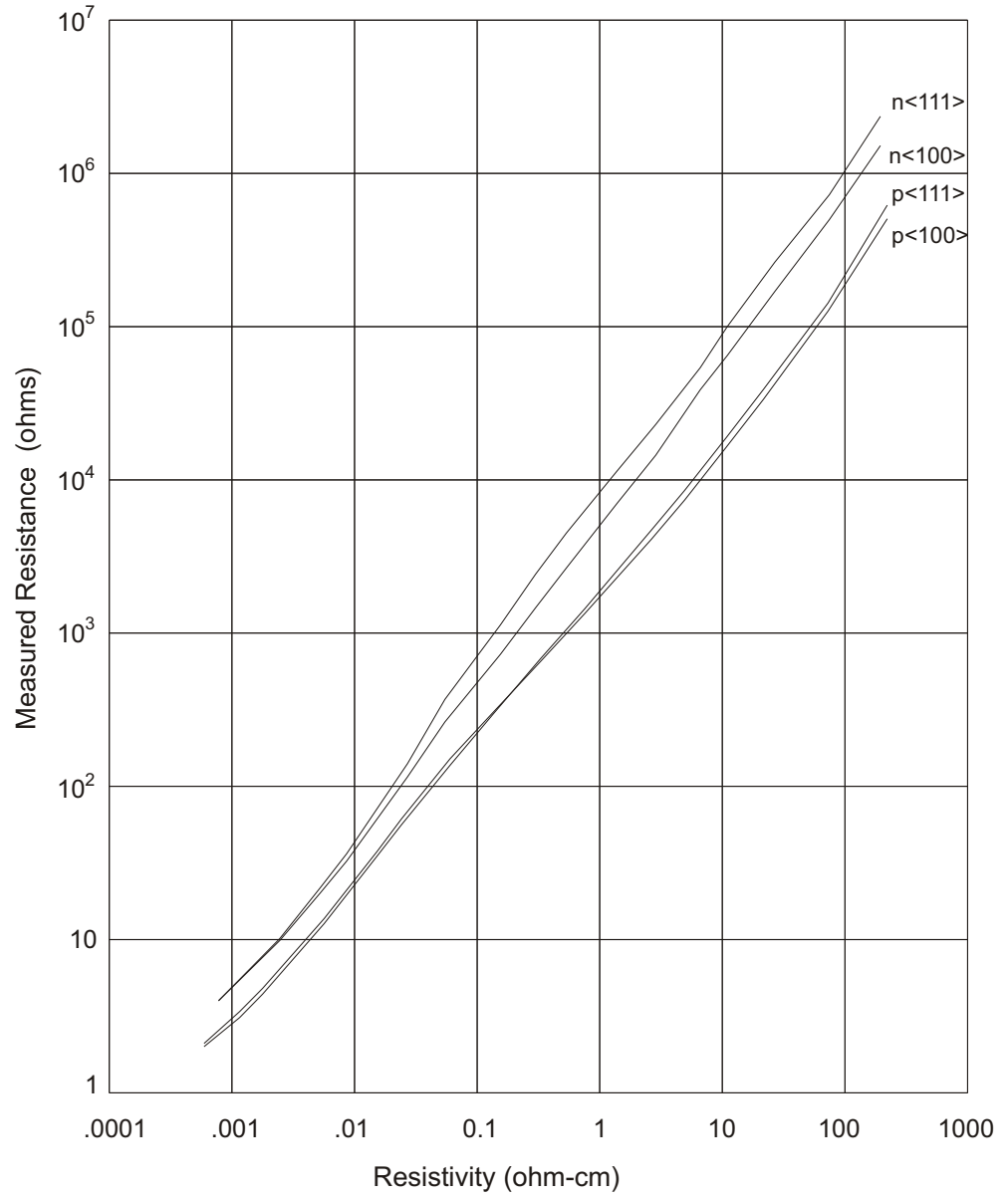
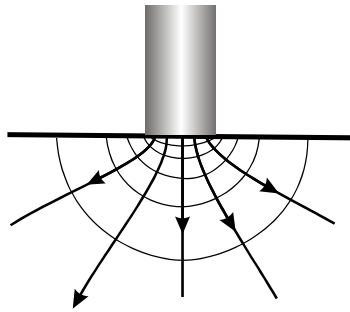
*What is the significance of resistivity? In a semiconductor it is related to the concentration of electrons and holes:*

$$= \frac{1}{\rho} = nq_e + pq_p$$

*And from that, the dopant concentration can be approximated.*

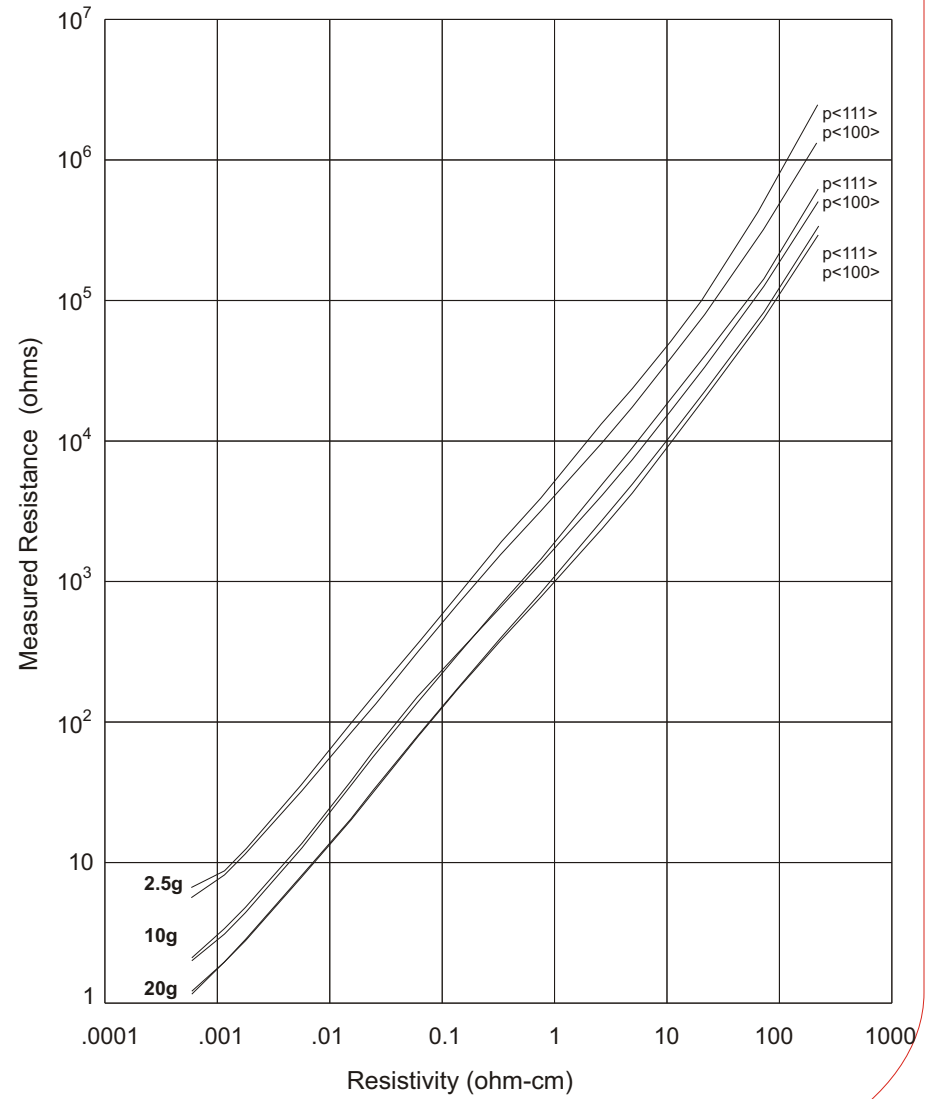
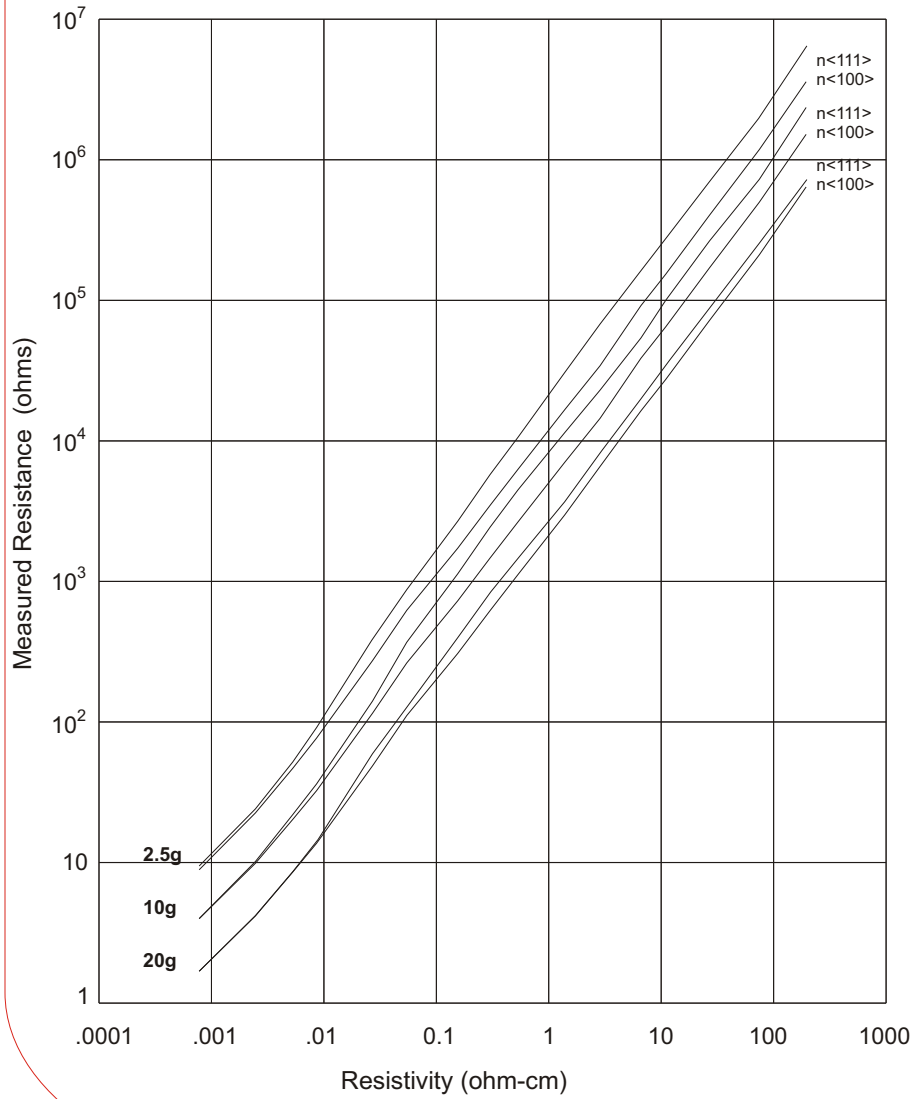
$$N \approx n \frac{1}{q_e}$$

# Calibration Chart Spreading Resistance vs. Resistivity (NIST Traceable Si Bulk Standards)



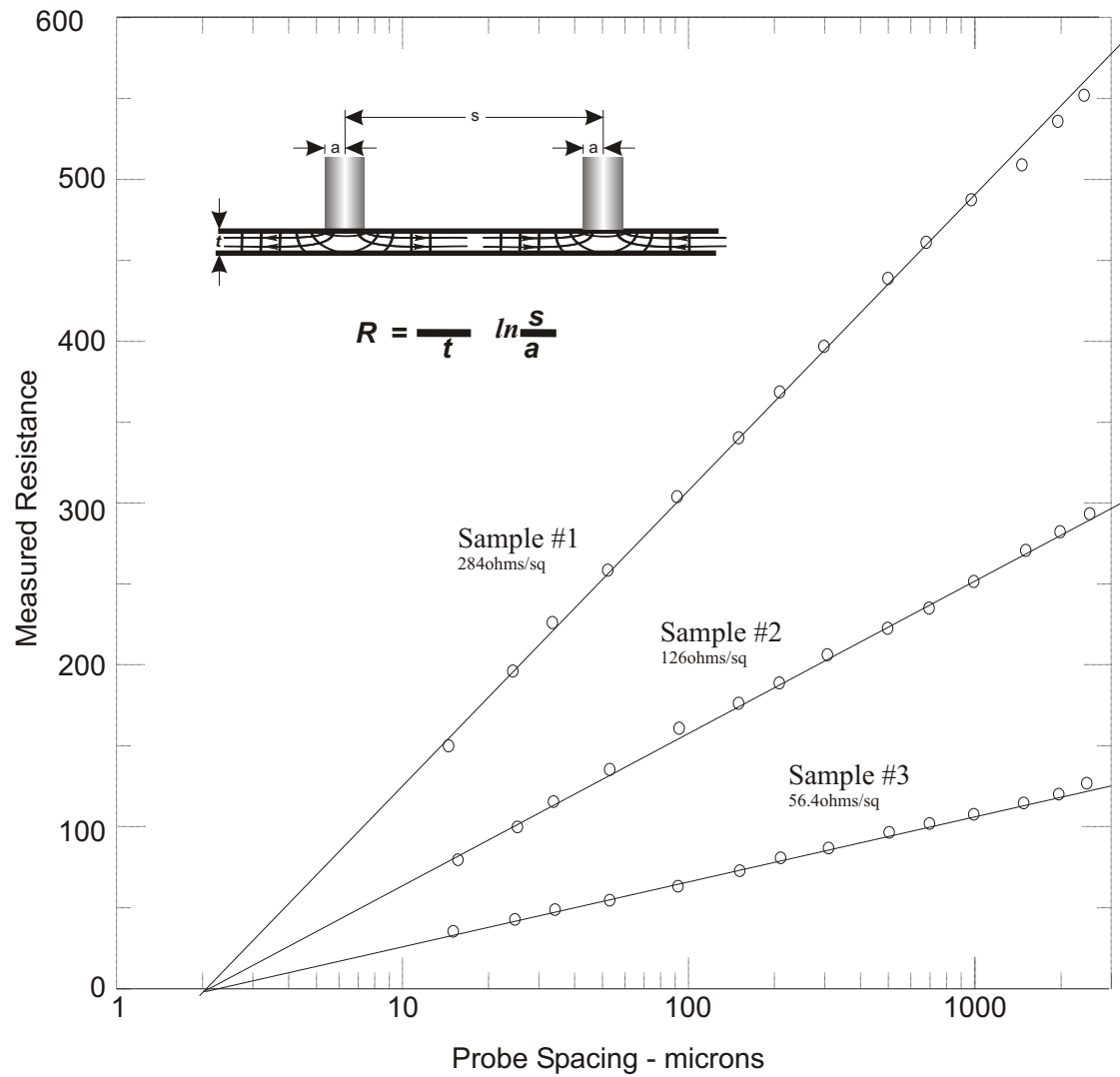


# Calibration Data for Three Probe Loads



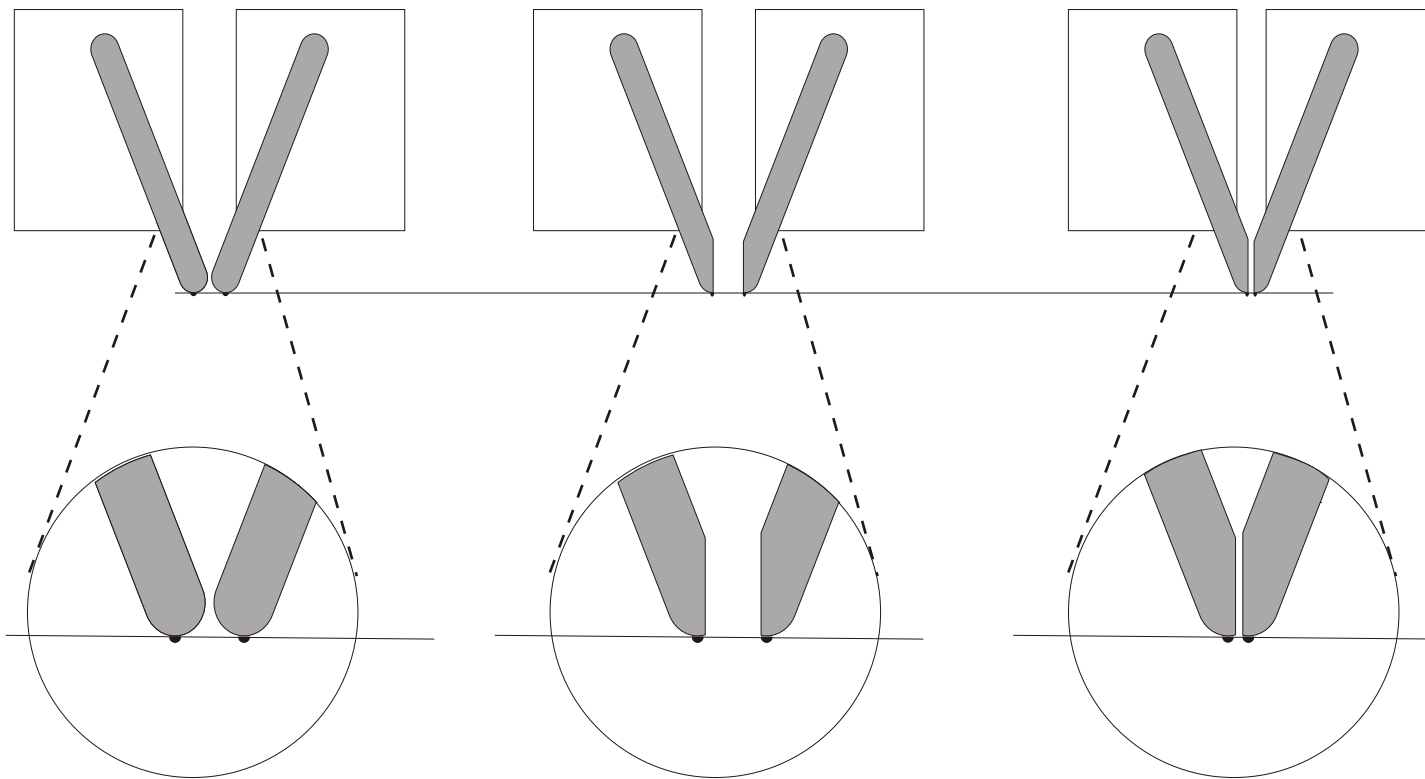
# Probe Spacing Experiment on Relatively Thin Layers

(Measured resistance is dominated by the lateral current flow)

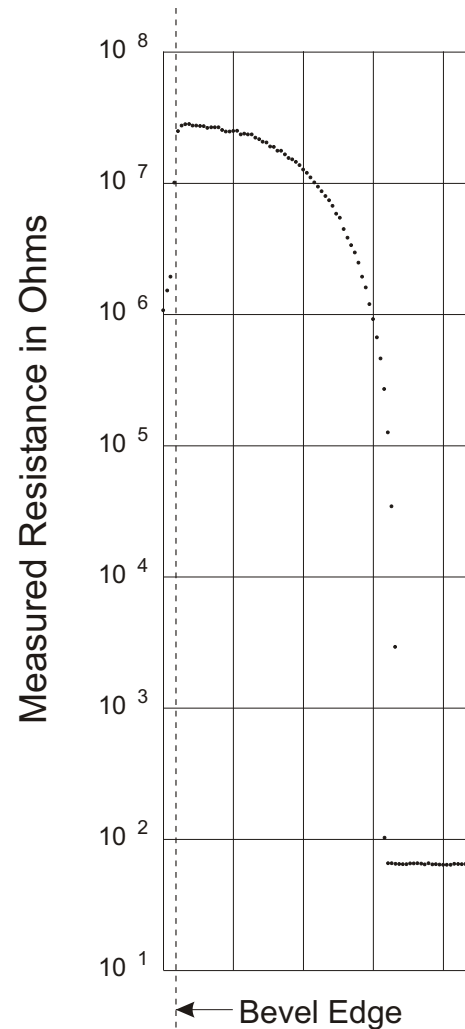
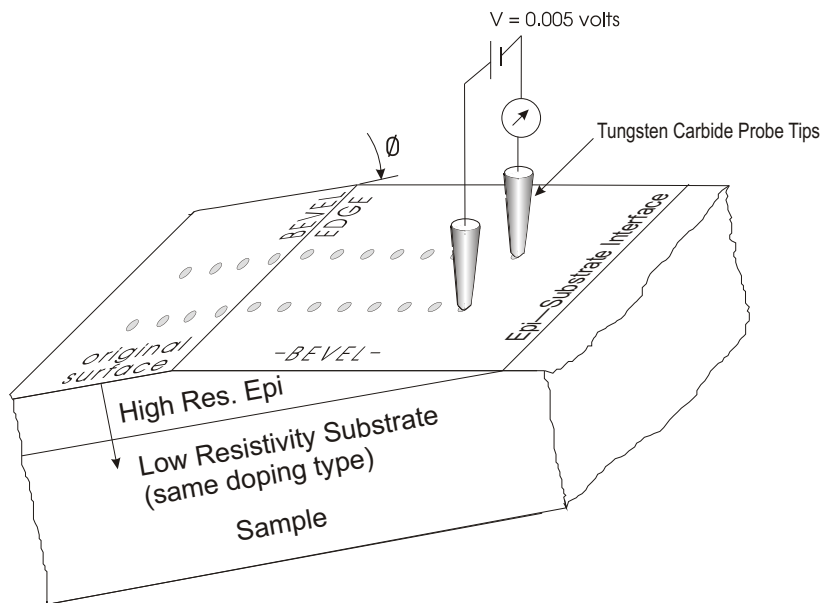


After: Dickey, NBS SP 400-48 p16

Simple diagram showing probe shaping to minimize probe separation



# High Resistivity Epi

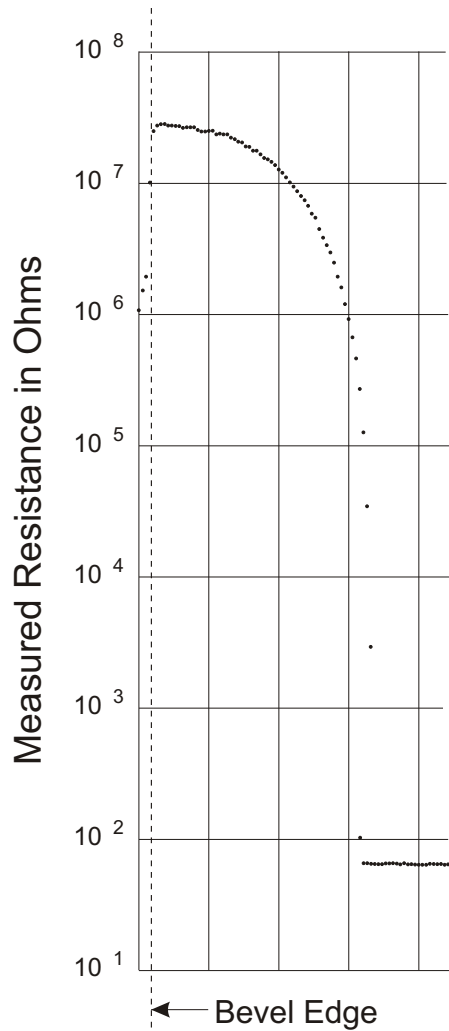


Probing

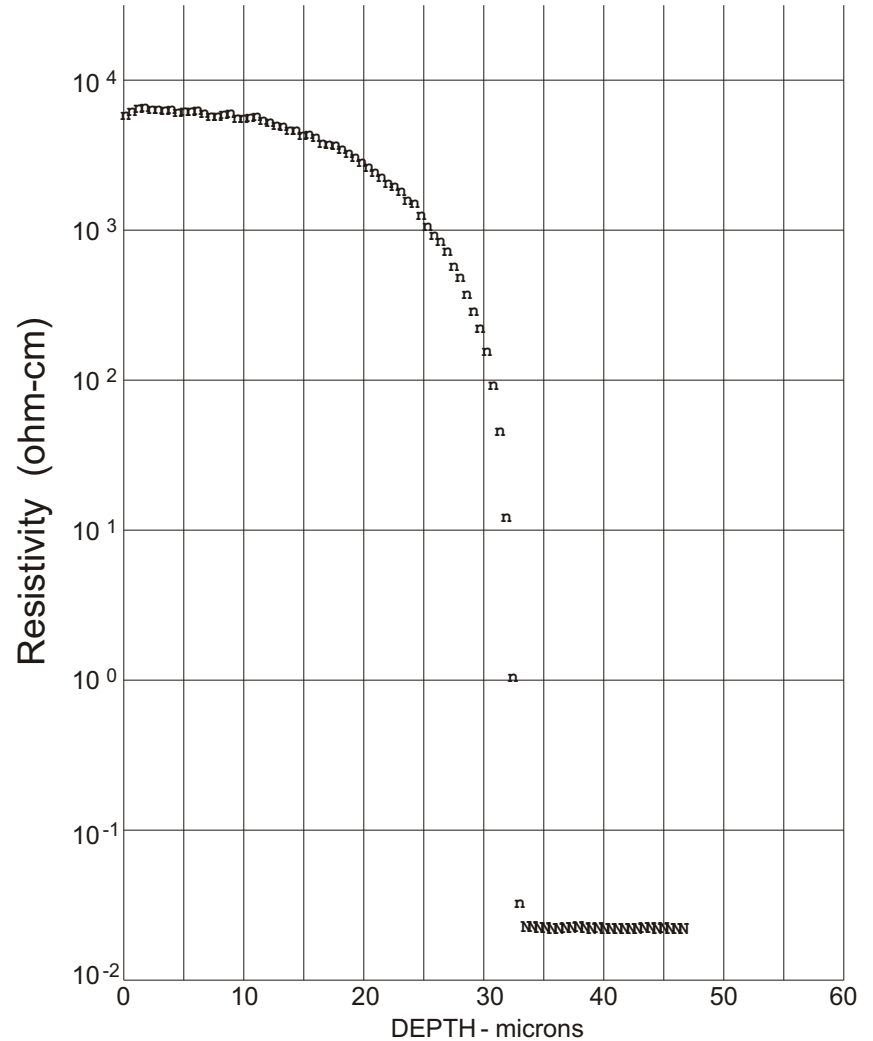


“Raw Data”

# High Resistivity Epi (continued)



*Data Reduction* →

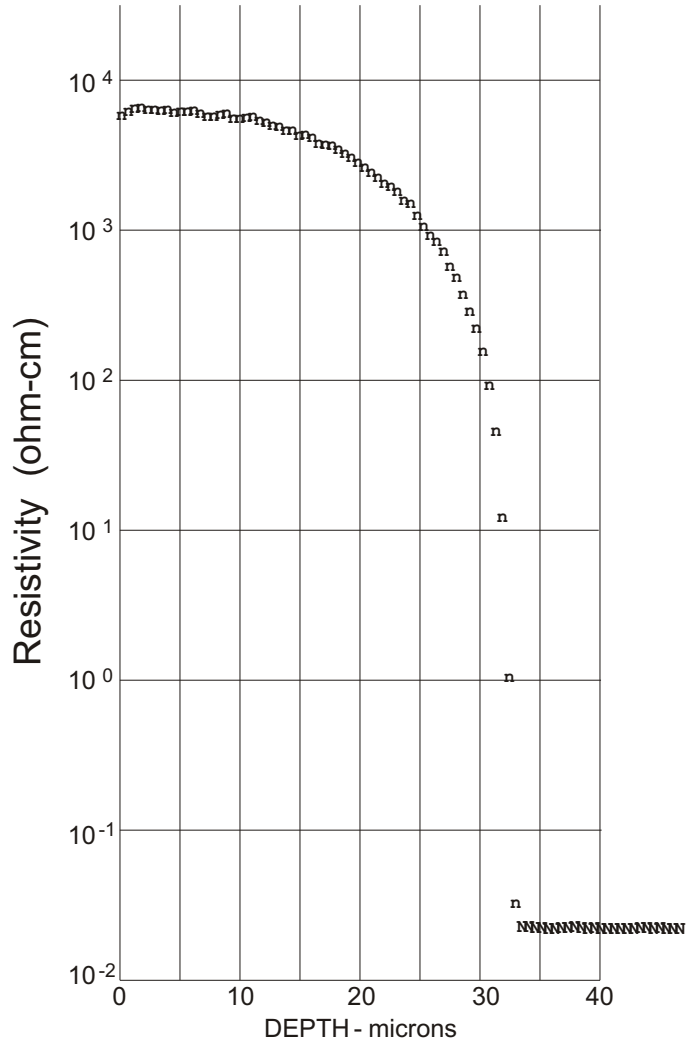


“Raw Data”

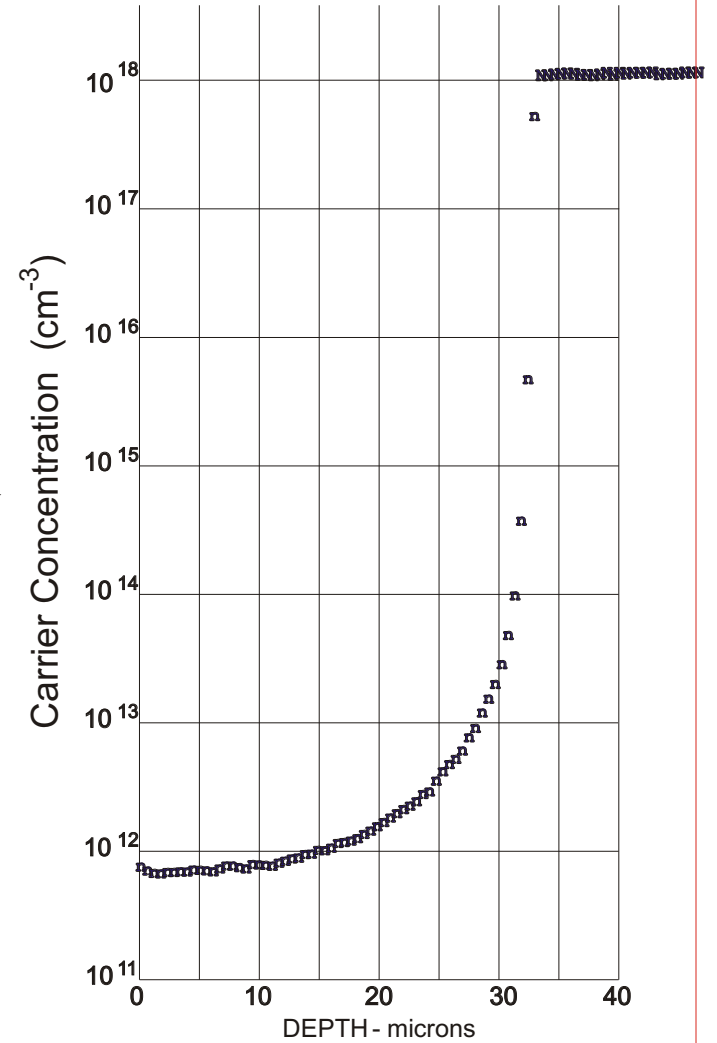


Resistivity Plot

# High Resistivity Epi (continued)



Carrier Concentration  
Calculated Using  
Published Carrier  
Mobility Values

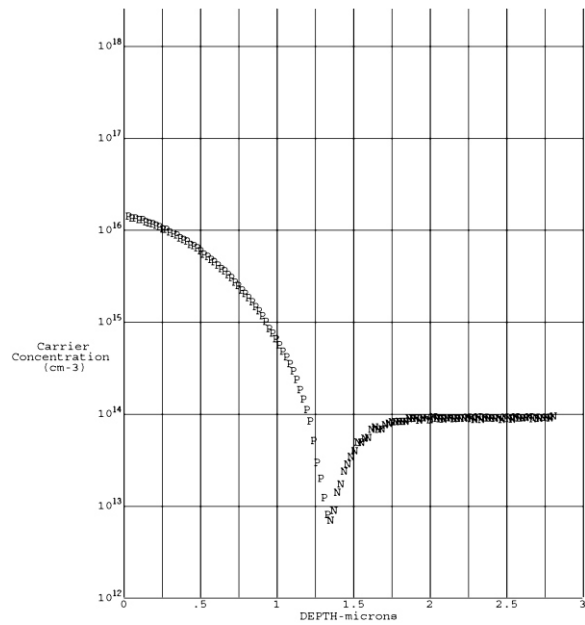


Resistivity

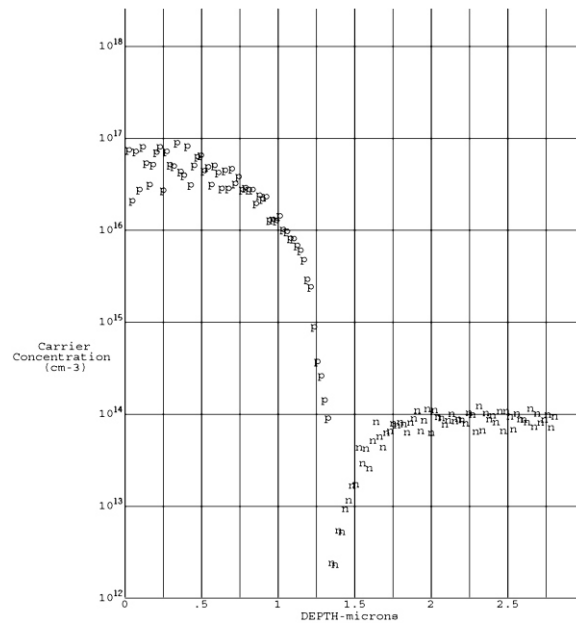


Carrier Concentration

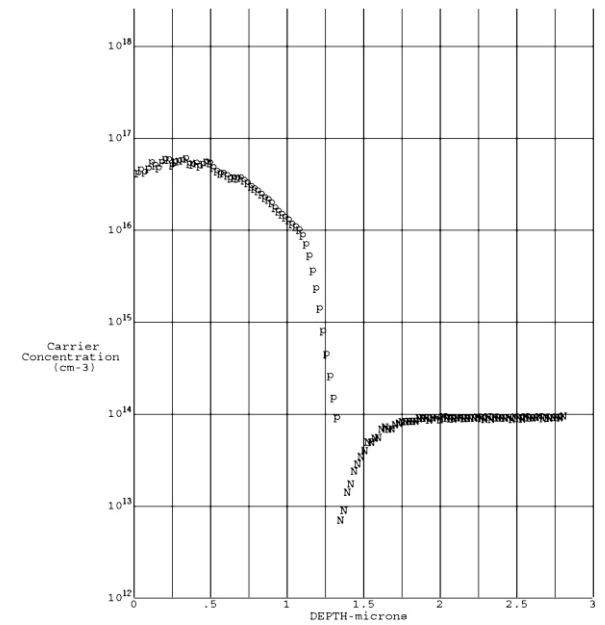
# Sampling Volume Correction



**Uncorrected layers  
(Unsmoothed data)**



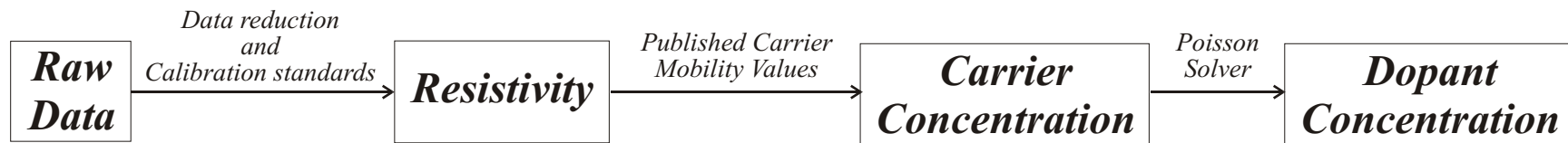
**Both layers corrected  
(Unsmoothed data)**



**Top layer corrected and smoothed  
(Uncorrected/unsmoothed substrate)**

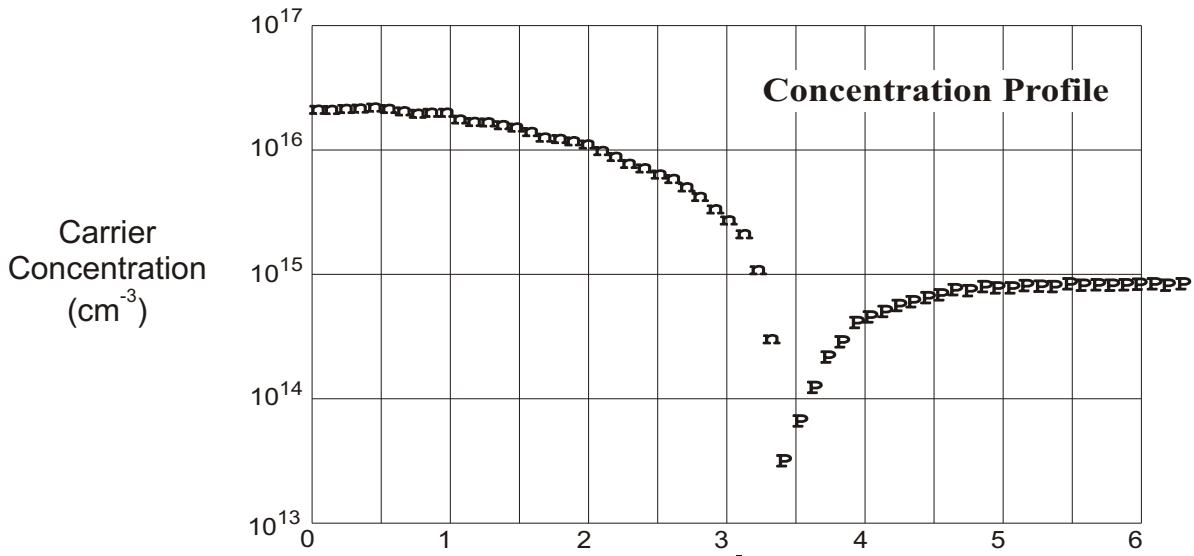
**Our correction algorithms account for the sampling volume on non-uniformly doped layers. In regions with slight to no resistivity gradient, the algorithms tend to magnify the mechanical noise. But without correction the graded layer's values can be very wrong! We have various levels of smoothing which we can use to reduce the scatter in your profiles.**

**SIMPLE CARRIER CONCENTRATION  
PROFILES CAN BE CONVERTED  
TO DOPANT PROFILES  
USING OUR POISSON SOLVER**

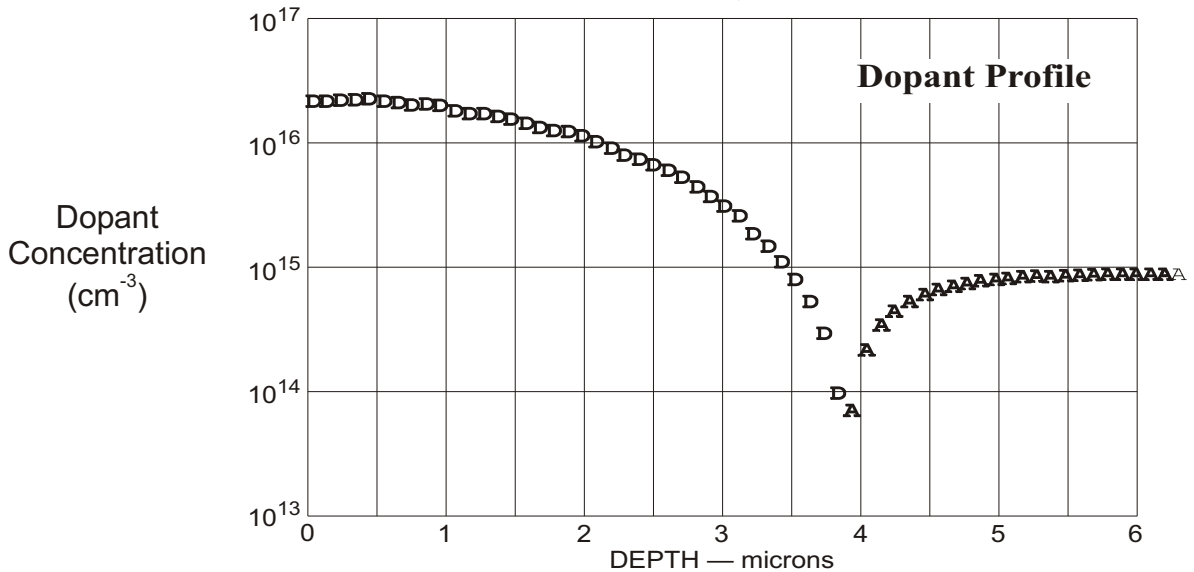




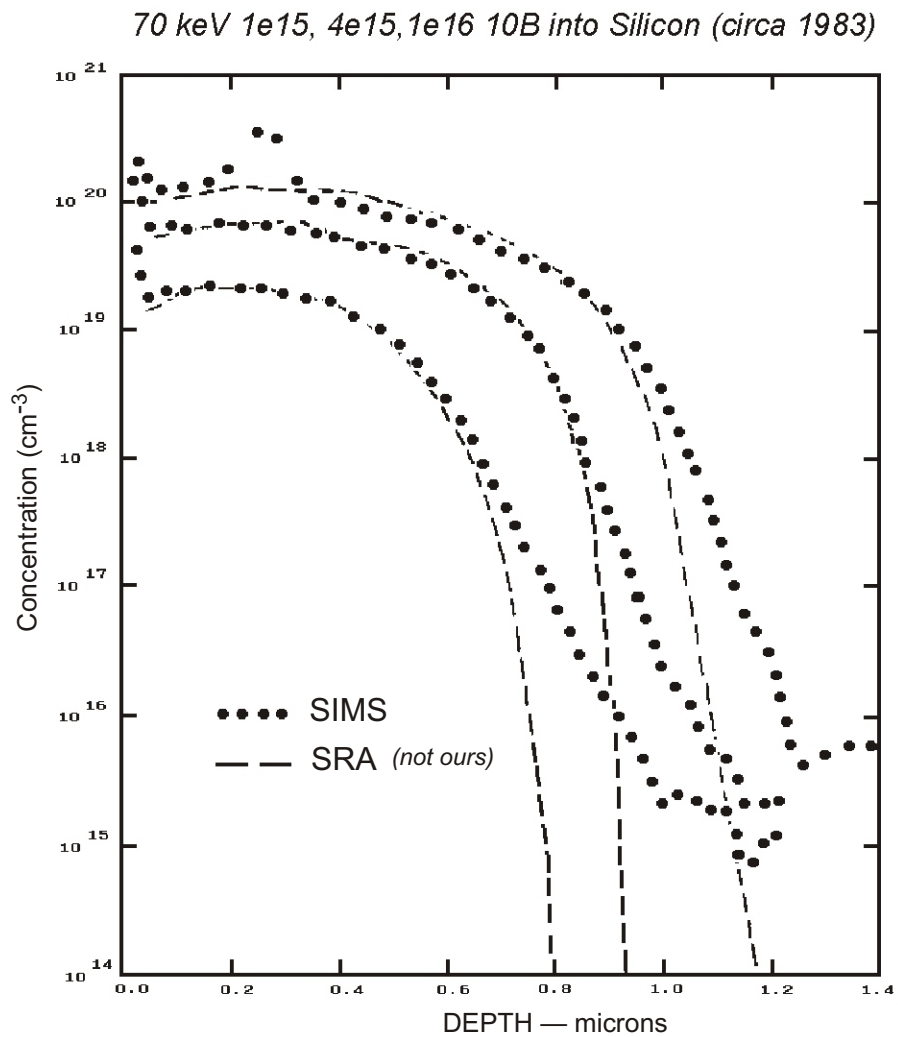
Simple Carrier Concentration Profiles Can Easily Be Converted to Dopant Profiles using Our Poisson Solver



Poisson Solver

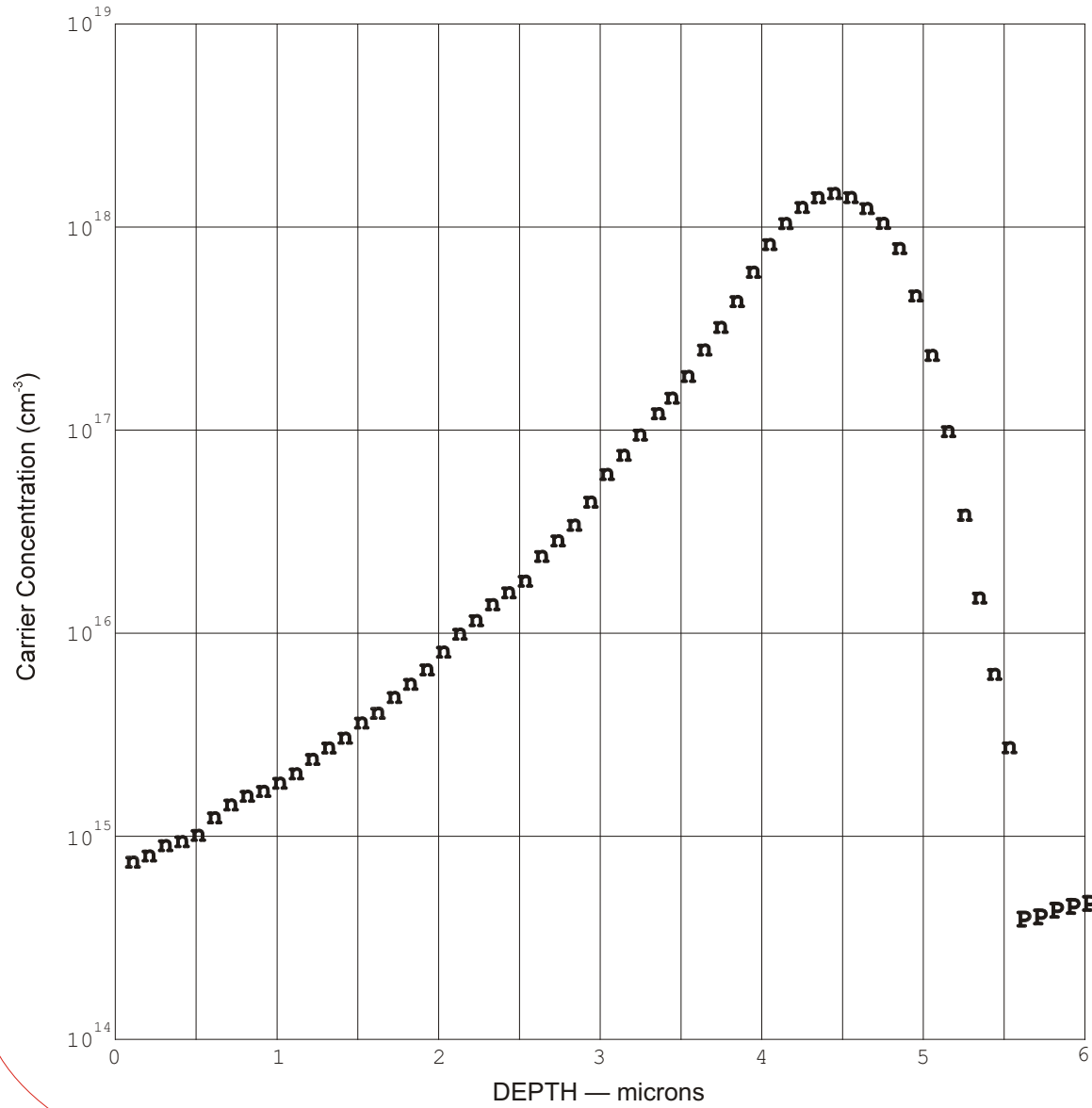


**SIMS Typically Reports Greater Depth in the Tail Region of B Diffusions. In the Following Example, Boron was Implanted into Single-crystal Si.**



From : James Ehrstein *et al*, ASTM Special Technical Publication 850, D. C. Gupta, editor, p. 415.

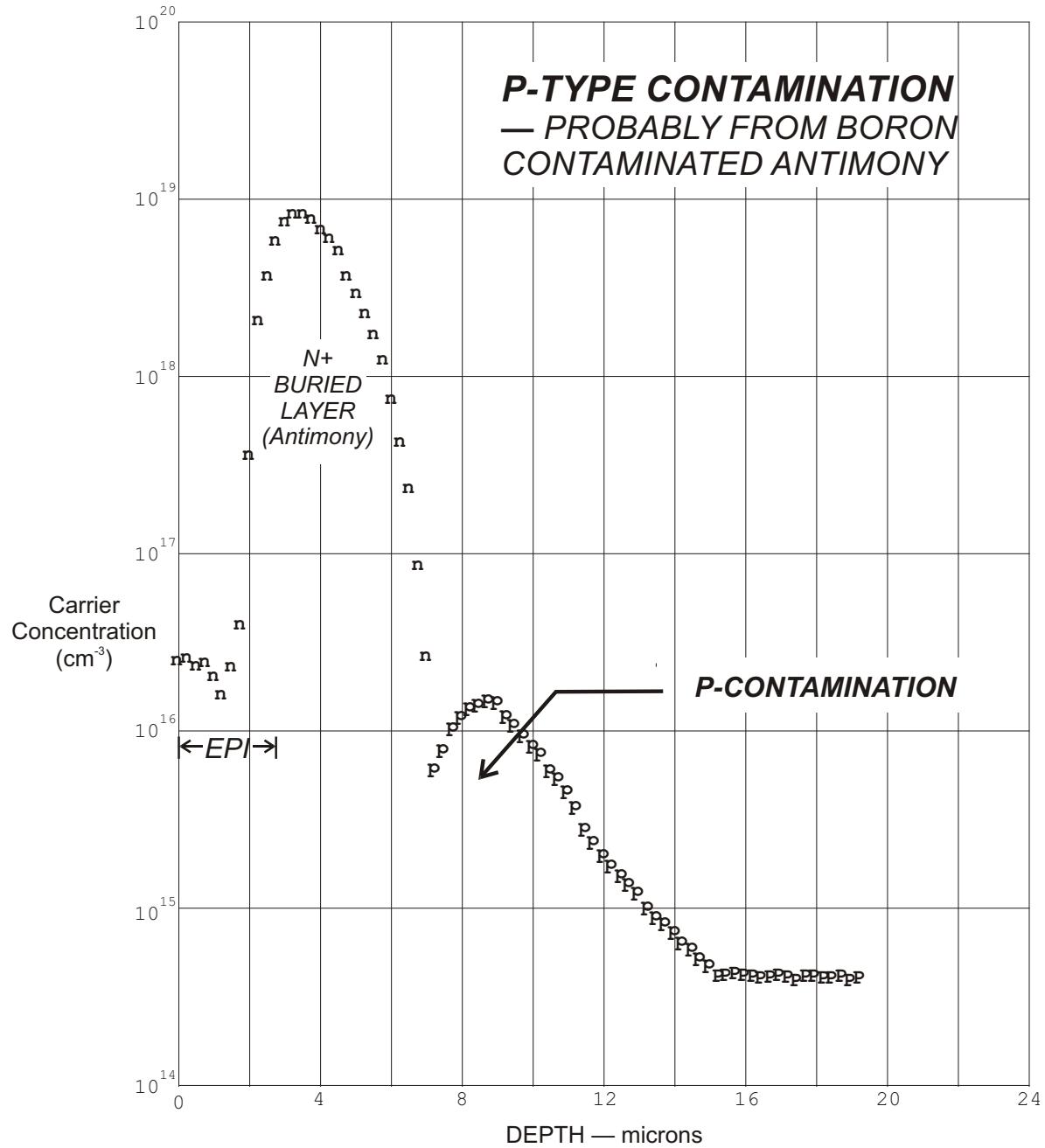
# 11 MeV Arsenic Implant



“The implantations were carried out using the facilities of the Lawrence Berkeley Laboratory. 11 MeV beams were obtained from a dynamatron with a 2.2 megavolt terminal. The ion source is a conducting crystal of gallium arsenide from which arsenic ions in the 5+ charge state were sputtered and extracted into the accelerator column.”

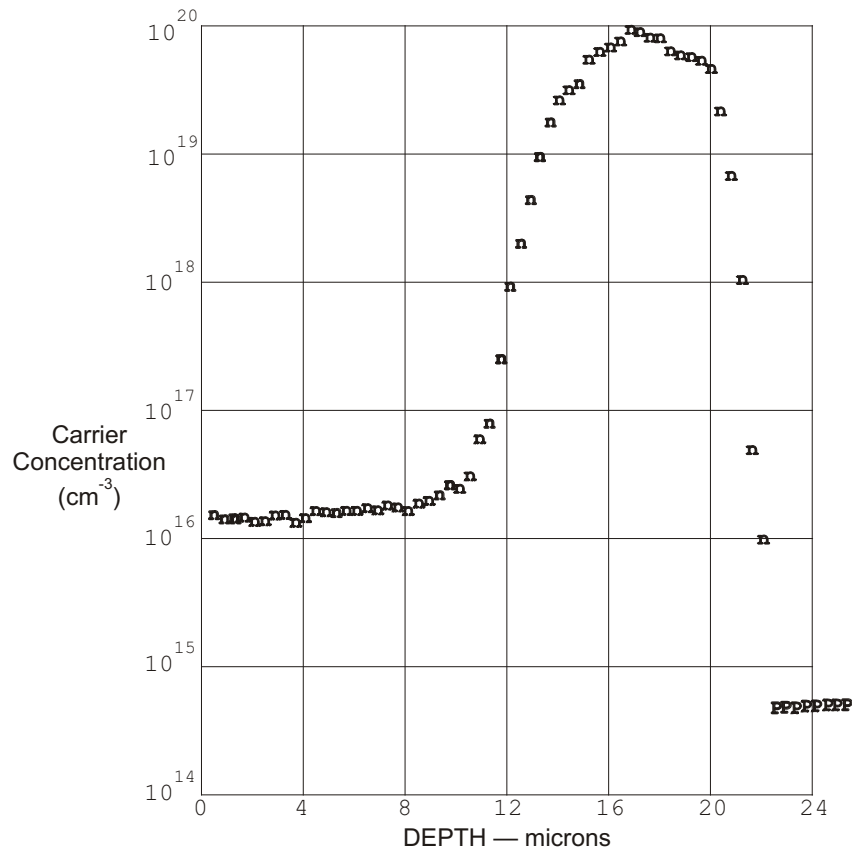
From *Megavolt Arsenic Implantation into Silicon*, a paper presented at the 1982 International Conference on Metallurgical Coatings and Process Technology by P.F. Byrne, N. W. Cheung, and D.K. Sadana, University of California, Berkeley.

*Many thanks to Peter Byrne for permission to reproduce and disseminate this very impressive profile.*

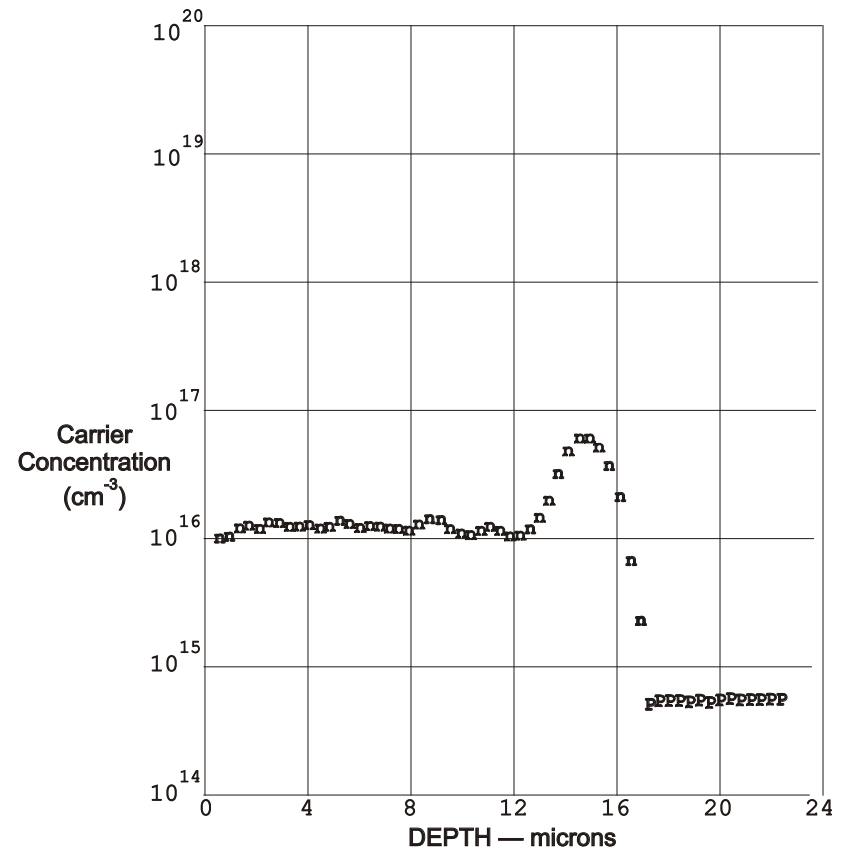


# Arsenic Autodoping During Epitaxial Deposition

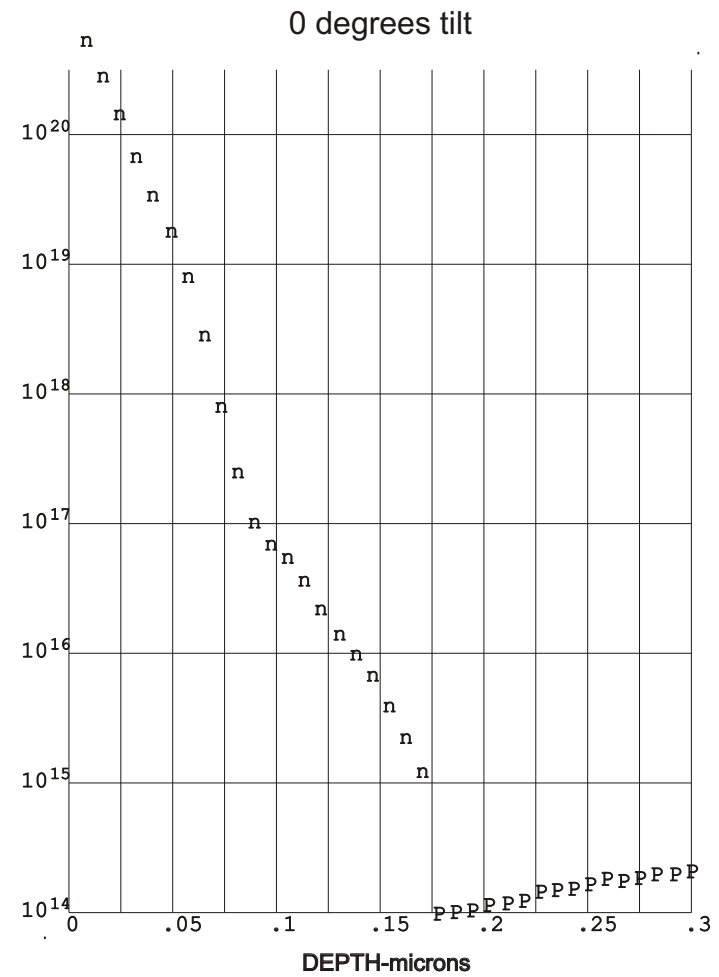
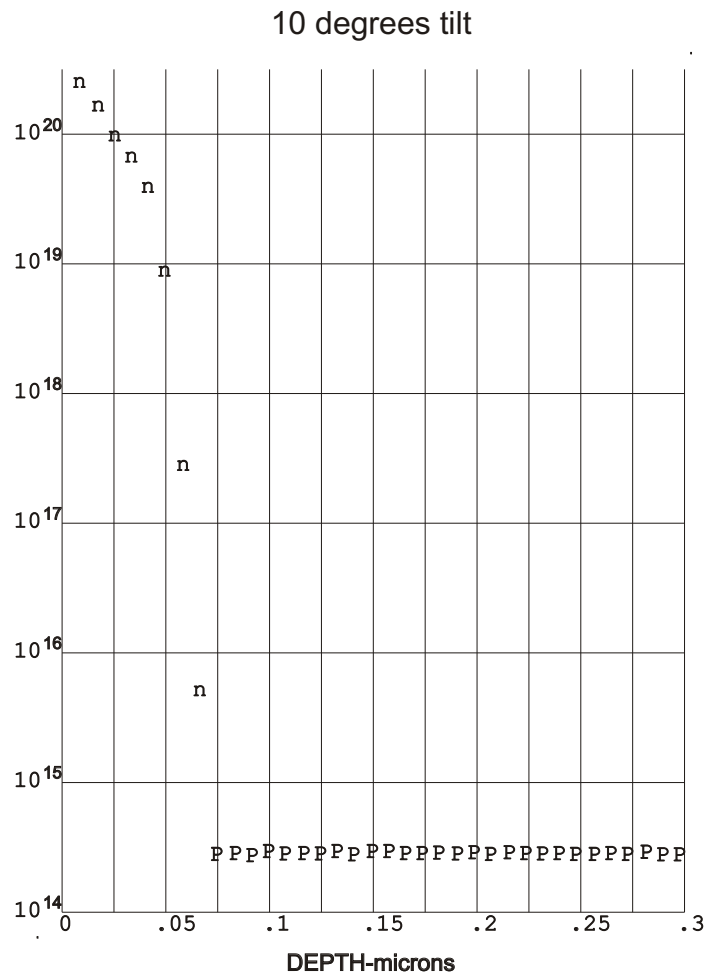
*SRP Through a Buried Layer Pattern:*



*SRP through the Field:*

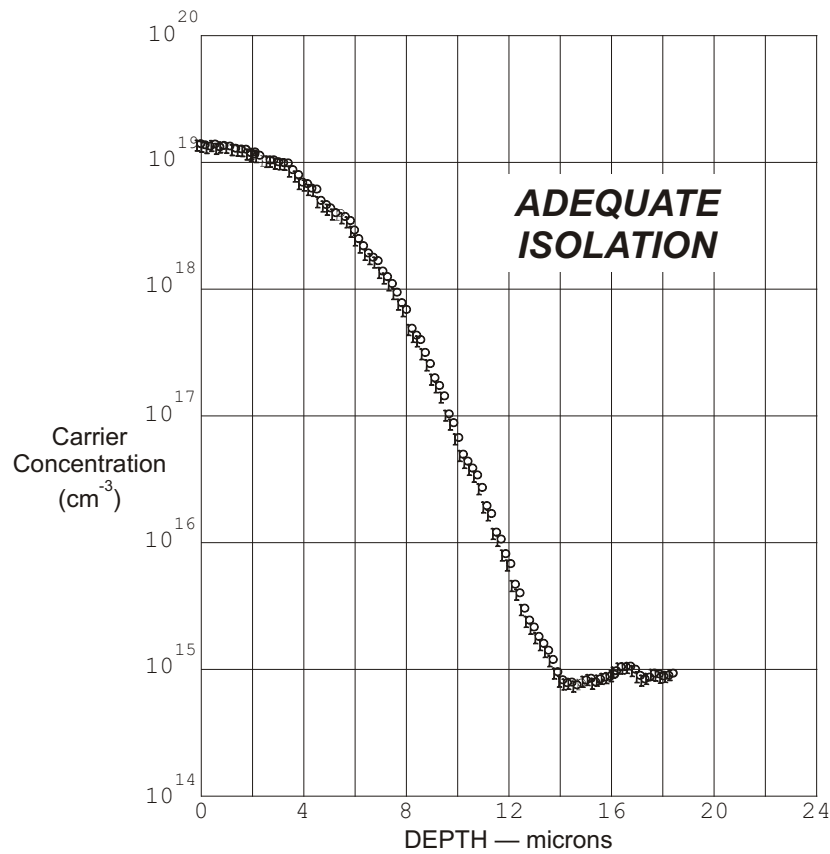


# Ion Implant Channeling

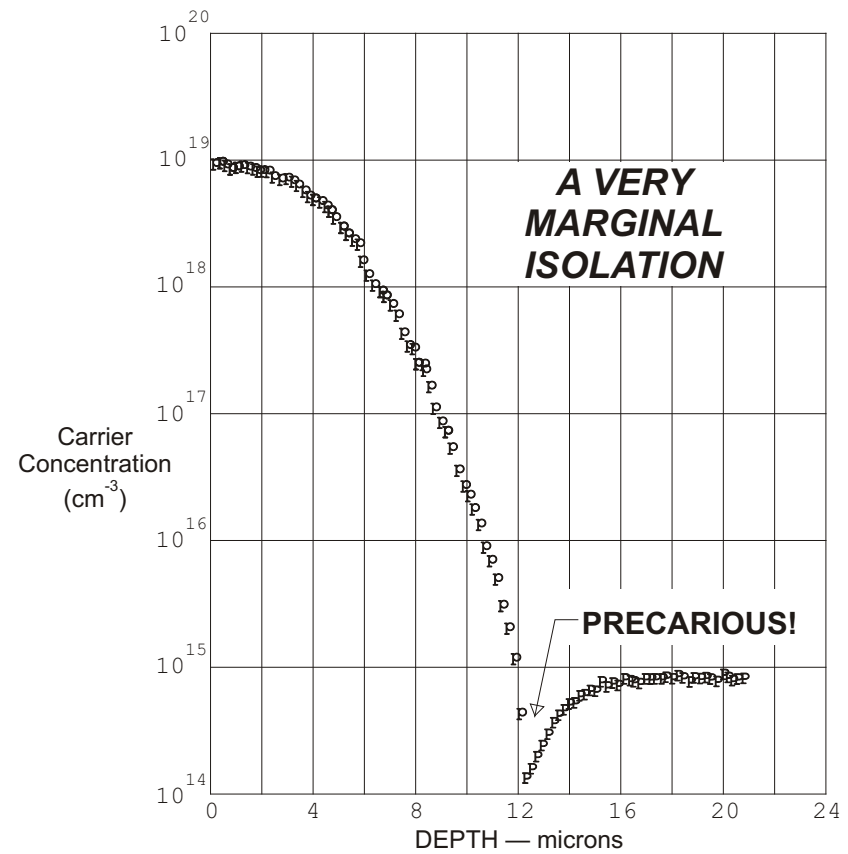


# ***P+ Isolation Diffusion into N-Epi***

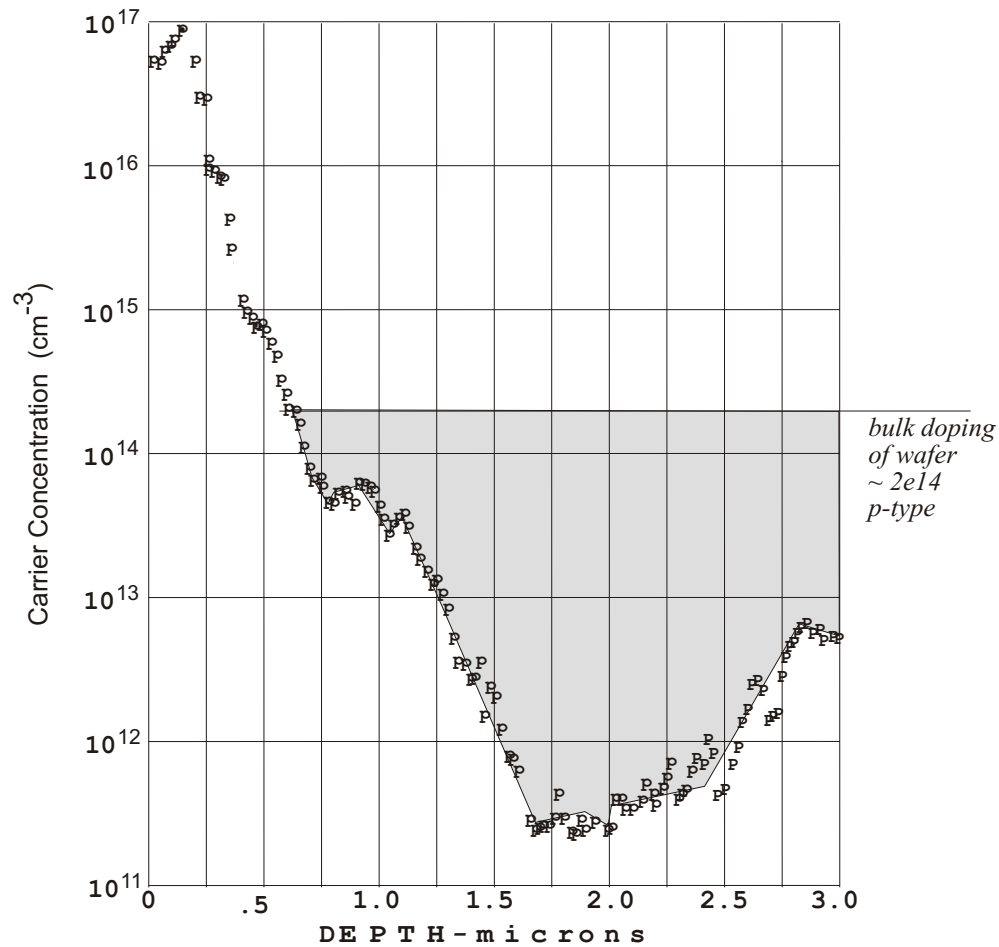
**Wafer A**



**Wafer B**



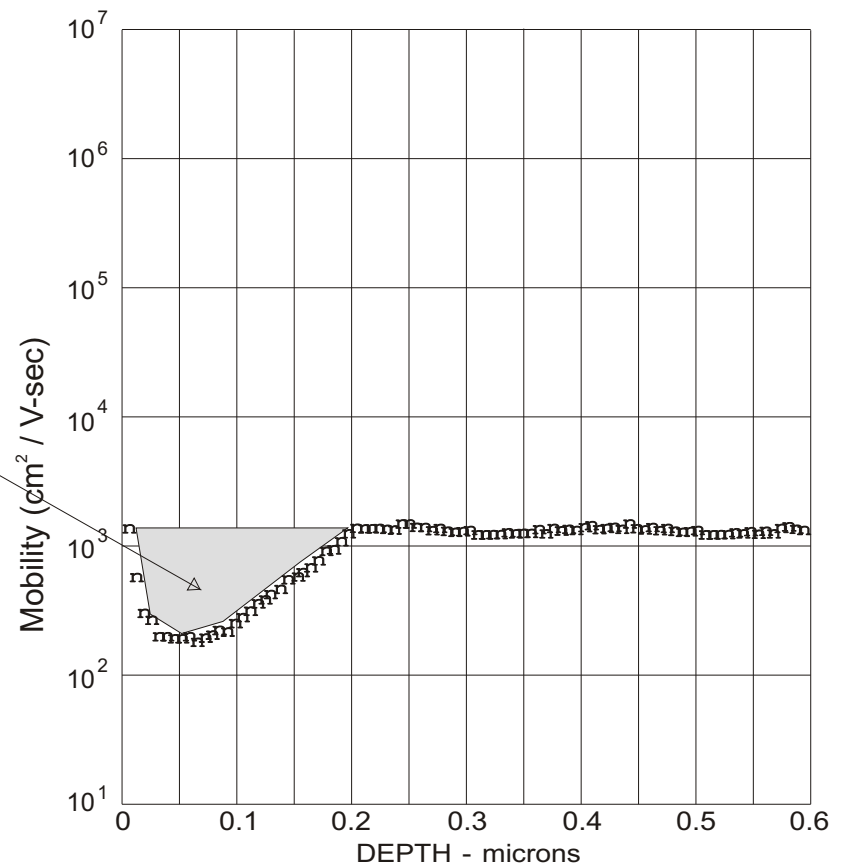
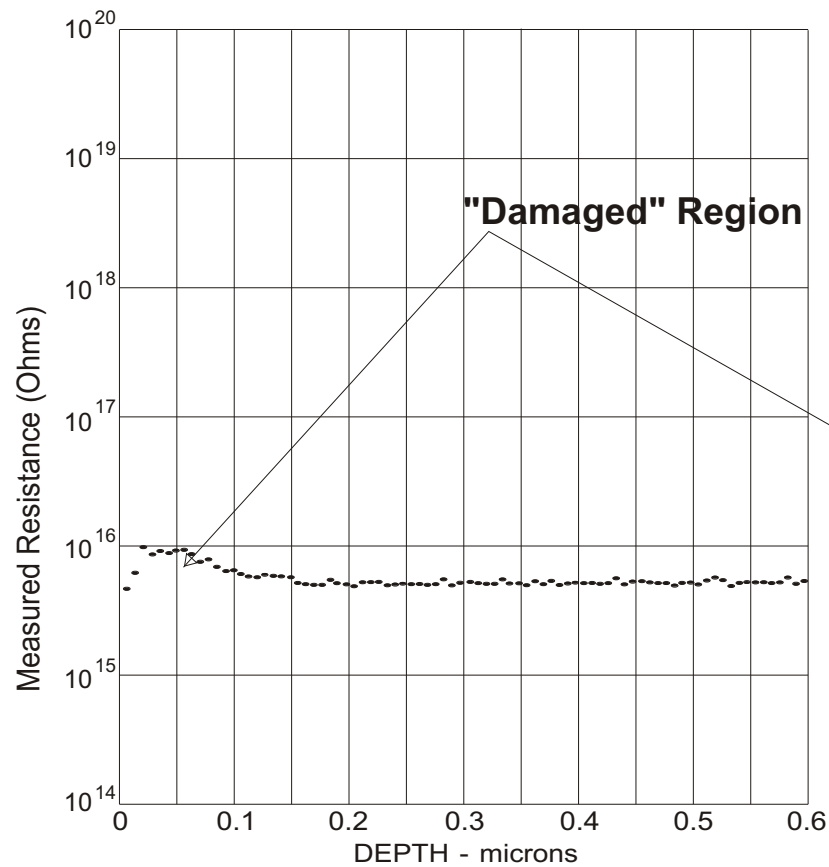
# Thermal Donors — A Severe Case



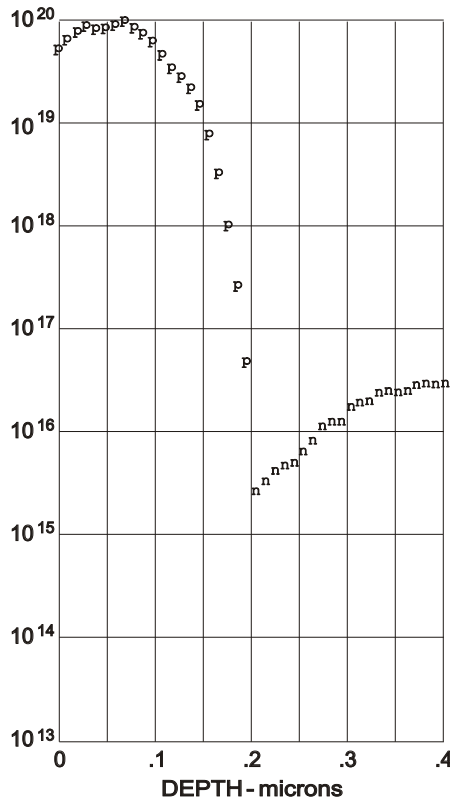


# Unannealed Implant

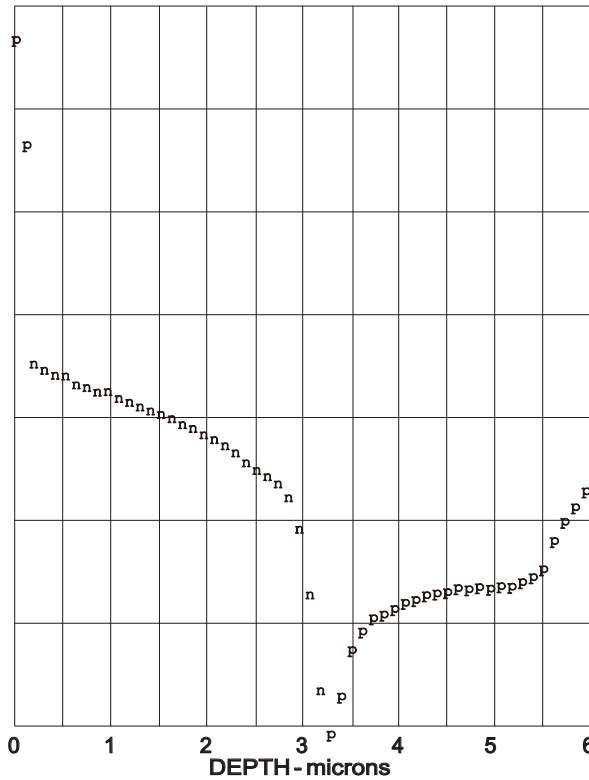
**N-type implant into  $1e16 \text{ cm}^{-3}$  N-type background. Since the implant wasn't activated, SRA senses the mobility change in the damaged area.**



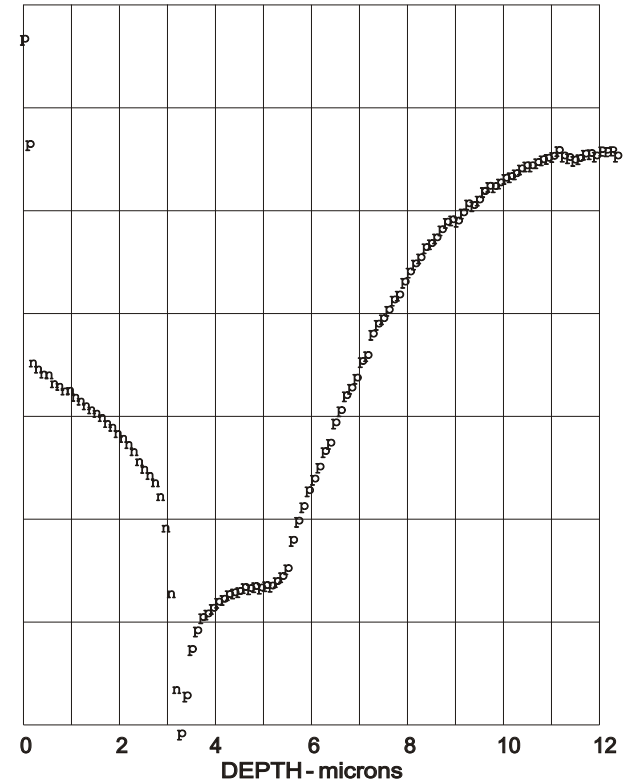
# CMOS (P-channel Source-Drain)



Shallow Profile to Characterize the Source-Drain

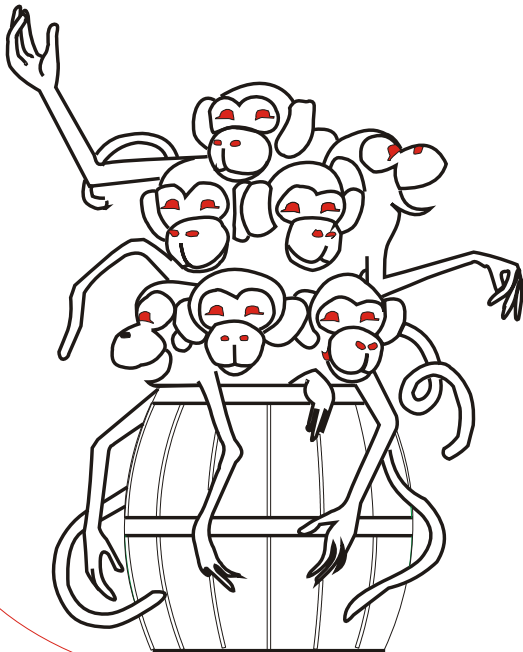


Steeper Profile (Plotted on 2 Depth Scales) to Characterize the N-Well, Epi, and Substrate



## *In Closing...*

- *Please Visit Us and Take the Tour*
- *SRA is Useful Whenever the Doping of Silicon is of Concern*
- *Web Page: [www.solecon.com](http://www.solecon.com)*



*Best Wishes from the Folks  
at Solecon Labs.*